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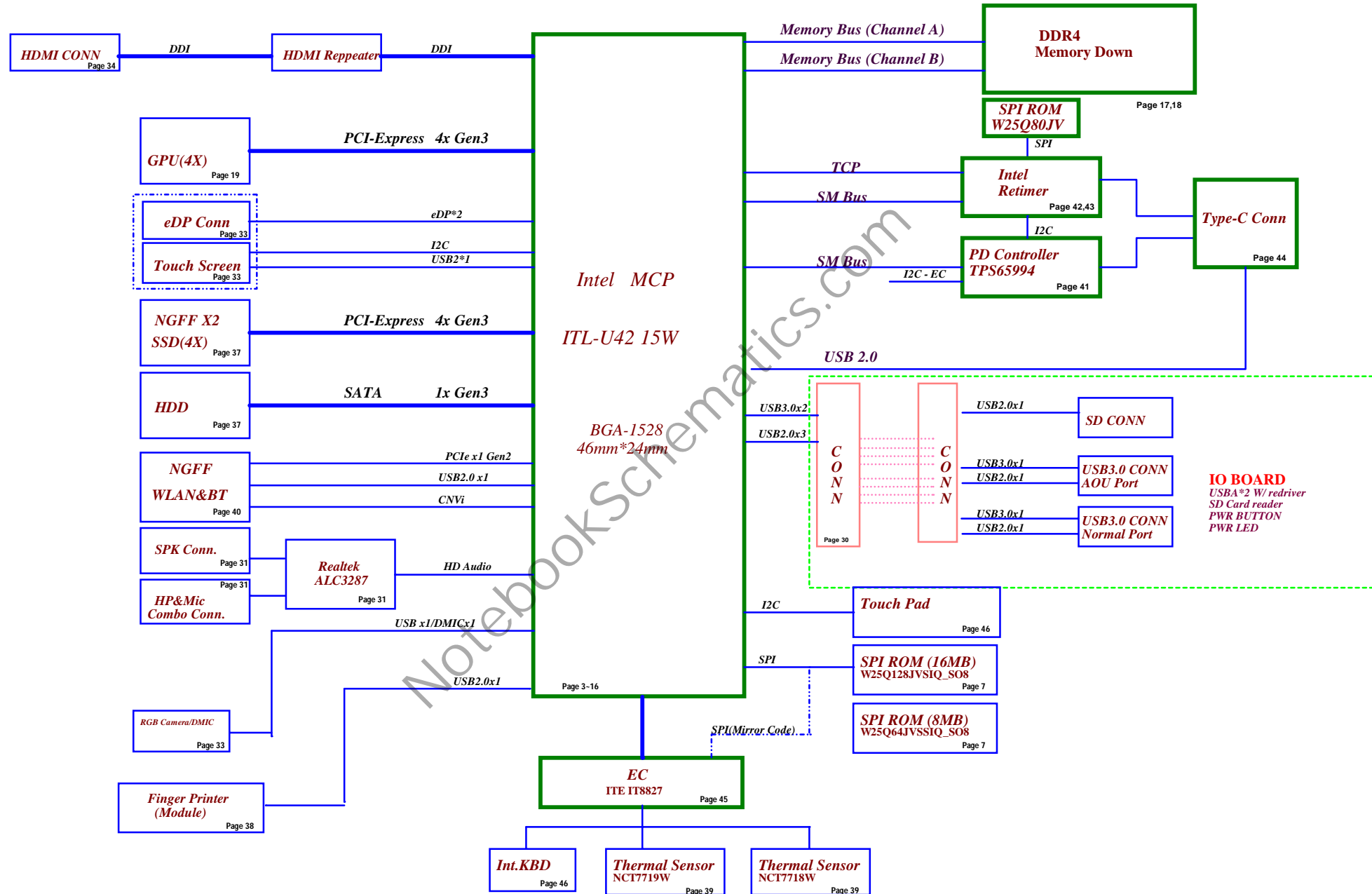
S550 MB Schematic Document

Tiger Lake_U42 with DDR4

2020-02
REV: 0.1

NotebookSchematics.com

Security Classification		LC Future Center Secret Data		Title		
Issued Date		2018/08/20	Deciphered Date	2016/08/20	S550-ITL	
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Size	Document Number				Rev	
C	Cover Page				0.1	
Date: Thursday, May 28, 2020				Sheet 1 of 61		

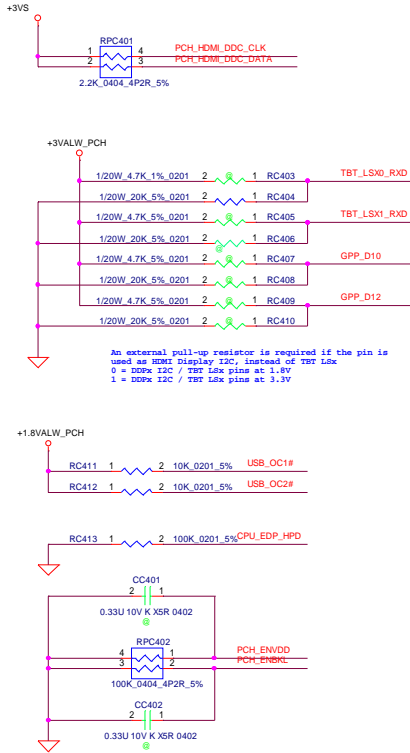
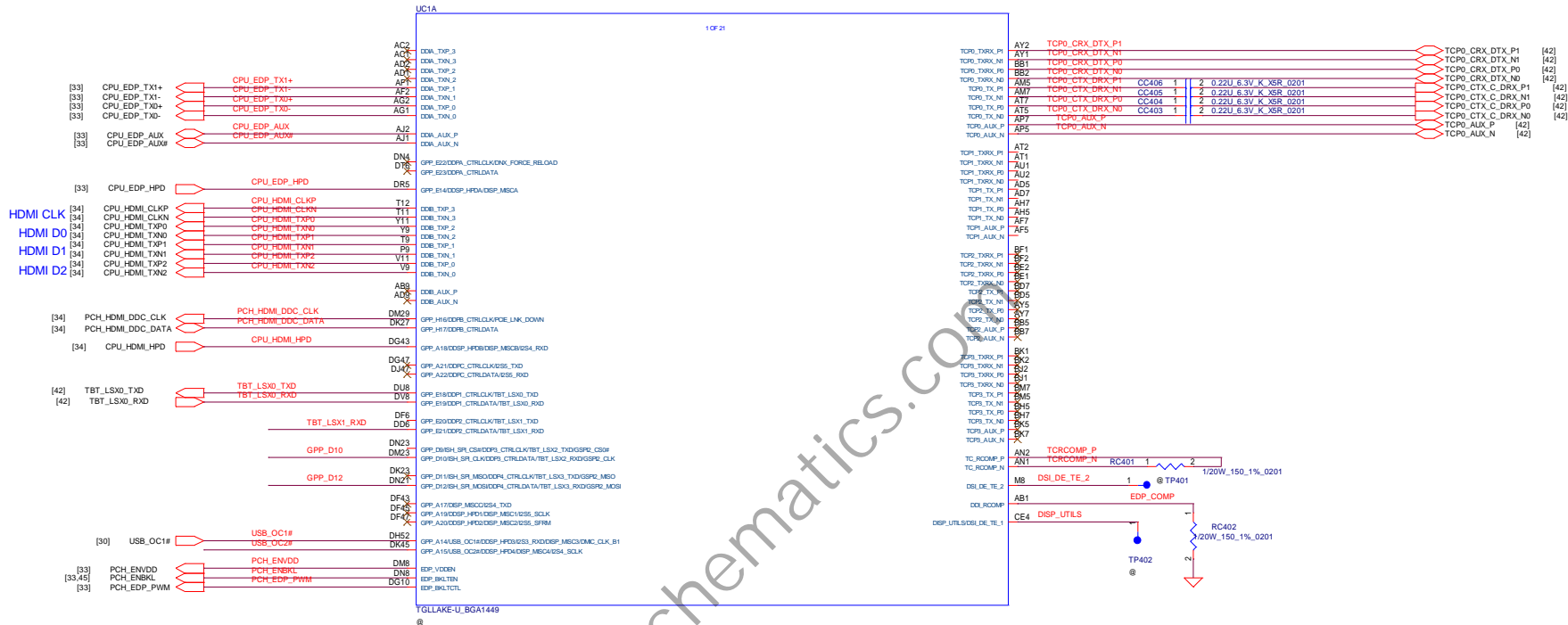


Voltage Rails (O --> Means ON , X --> Means OFF)						
Power Plane						
State	V9B+	+3VALW +5VALW	+1.8VALW +3ALW_PCH	+1.2V +2.5V_DDR +VCCST +VCCIN +VCCIN_AUX	+5VS +3VS +1.8VS +0.6VS	+VCCSTG
S0	O	O	O	O	O	O
S0IX	O	O	O	O	O	X
S5 S4 AC Only	O	O	O	X	X	X
S5 S4 Battery only	O	O	X	X	X	X

[illegible]

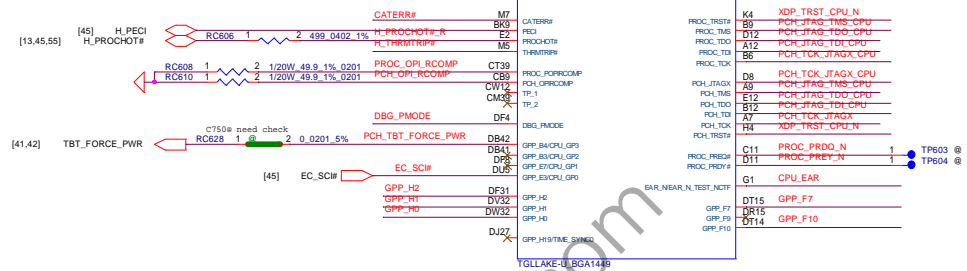
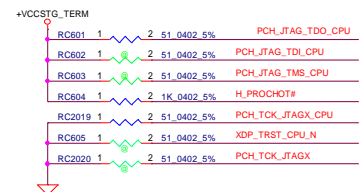
Device	Address	Device	Address	Device	Address	Device	Address
Smart Battery	need to update	Thermal Sensor(NCT7719W)	1001_101xb	PMC	0X34	PD	
Charger	0001_001xb	Thermal Sensor(NCT7718W)	1001_100xb				
Battery	0x34	GPU	0x9E				

HSIO PORT		Function
USB3.0	1	USB Type-C1
	2	USB Type-A AOU
	3	USB Type-A
	4	USB Type-C2
	5	NC
	6	NC
USB2.0	1	USB Type-A AOU
	2	USB Type-A
	3	NC
	4	Finger Printer
	5	NC
	6	NC
	7	CAMERA
	8	USB Type-C1
	9	USB Type-C2
	10	BT
PCIE	1-8	1-4 SUB3.0 5-4 NC
	9	WLAN
	10-12	NC
	13-16 X4	SSD-2

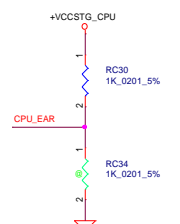


GPIO Group	Power Supply
GPP_A	1.8V
GPP_B/C/D/E	3.3V
GPP_F	1.8V(only)
GPP_G/H	3.3V
GPP_R/S	1.8V
GPD	3.3V(only)

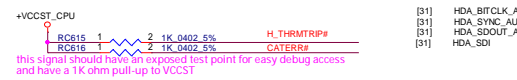
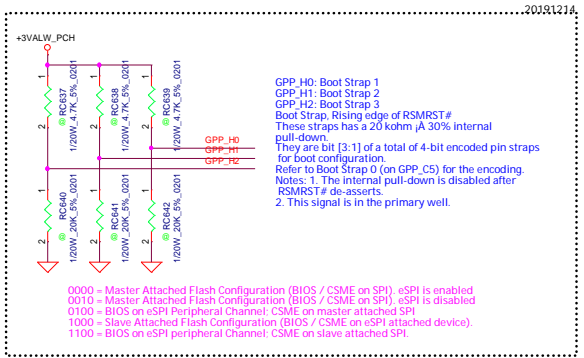




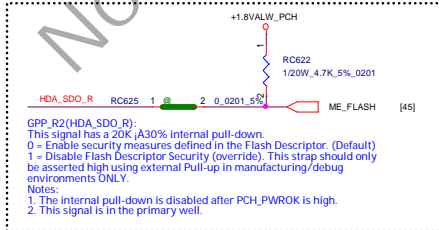
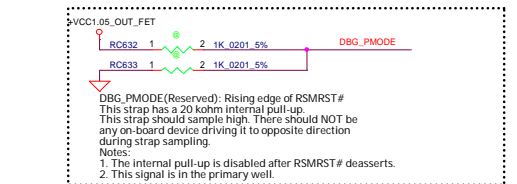
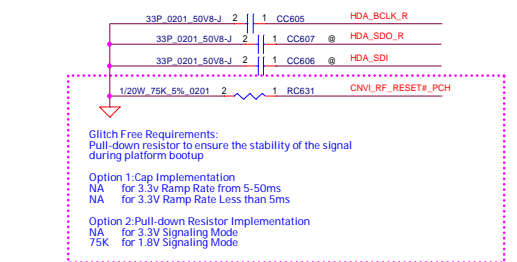
EAR
Stall CPU reset sequence
until de-asserted:
- 1 = (Default) Normal
Operation: No stall.
- 0 = Stall



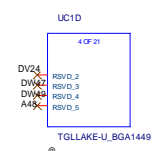
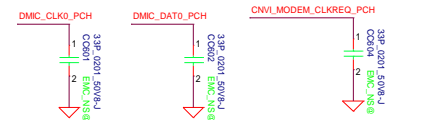
GPP_F7 and GPP_F10:
Reserved. Rising edge of RSMRST#
This strap has a 20 kohm \pm 30% internal pull-down.
This strap should sample LOW. There should NOT be any on-board device driving it to opposite direction during strap sampling.
Notes: 1. The internal pull-down is disabled after RSMRST# de-asserts.
2. This signal is in the primary well.

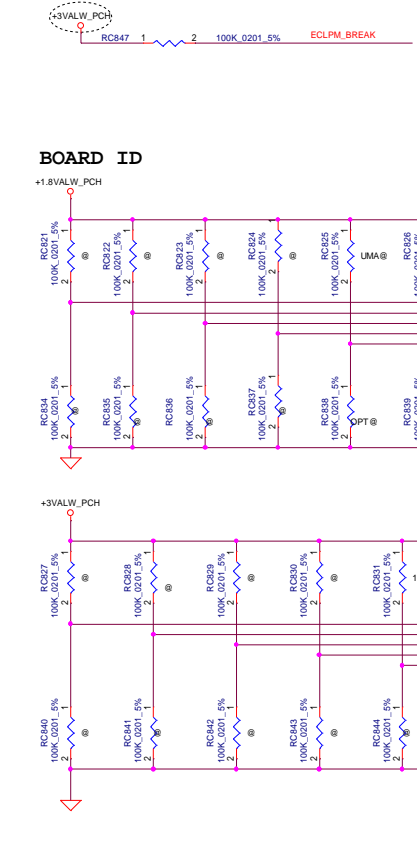
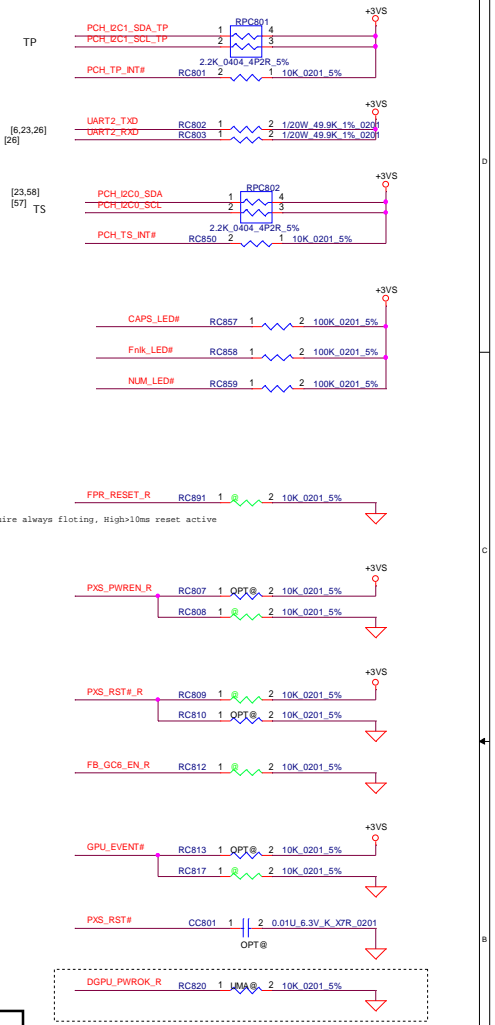
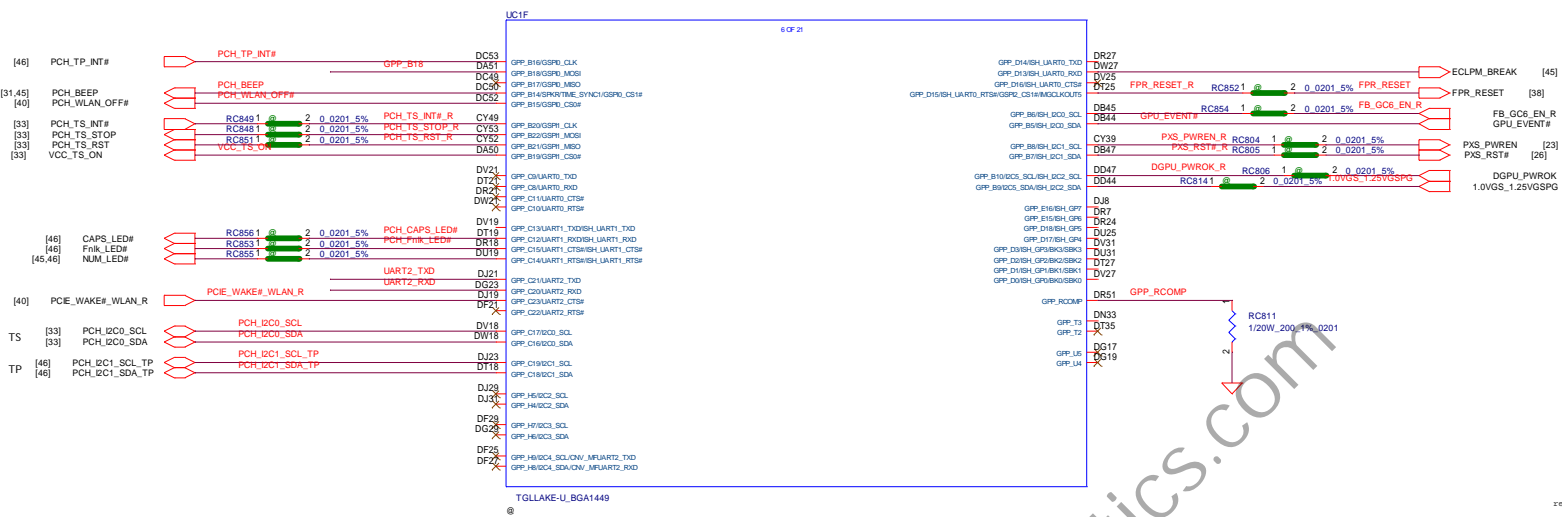


this signal should have an exposed test point for easy debug access and have a 1K ohm pull-up to VCCST



GPP_R2(HDA_SDO_R):
This signal has a 20K (\pm 30%) internal pull-down.
0 = Enable security measures defined in the Flash Descriptor. (Default)
1 = Disable Flash Descriptor Security (override). This strap should only be asserted high using external Pull-up in manufacturing/debug environments ONLY.
Notes:
1. The internal pull-down is disabled after PCH_PWROK is high.
2. This signal is in the primary well.





GPP_B14(PCH_BEEP):
Rising edge of PCH_PWROK
The strap has a 20 kohm A 30% internal pull-down.
0 = Disable Top Swap mode. (Default)
1 = Enable Top Swap mode. This inverts an address on access to SPI and firmware hub, so the processor believes it fetches the alternate boot block instead of the original boot-block. PCH will invert A16 (default) for cycles going to the upper two 64-KB blocks in the FWB or the appropriate address lines (A16, A17, or A18) as selected in Top Swap Block size soft strap.
Notes:
1. The internal pull-down is disabled after PCH_PWROK is high.
2. Software will not be able to clear the Top Swap bit until the system is rebooted.
3. The status of this strap is readable using the Top Swap bit (GPP0, Device 31, Function0, offset 0ch, bit4).
4. This signal is in the primary well.

GPP_B18: Rising edge of PCH_PWROK
The signal has a weak internal pull-down.
0 = Disable No Reboot mode. (Default)
1 = Enable No Reboot mode (PCH will disable the TCO Timer system reboot feature). This function is useful when running ITP/ADP.
Notes:
1. The internal pull-down is disabled after PCH_PWROK is high.
2. This signal is in the primary well.

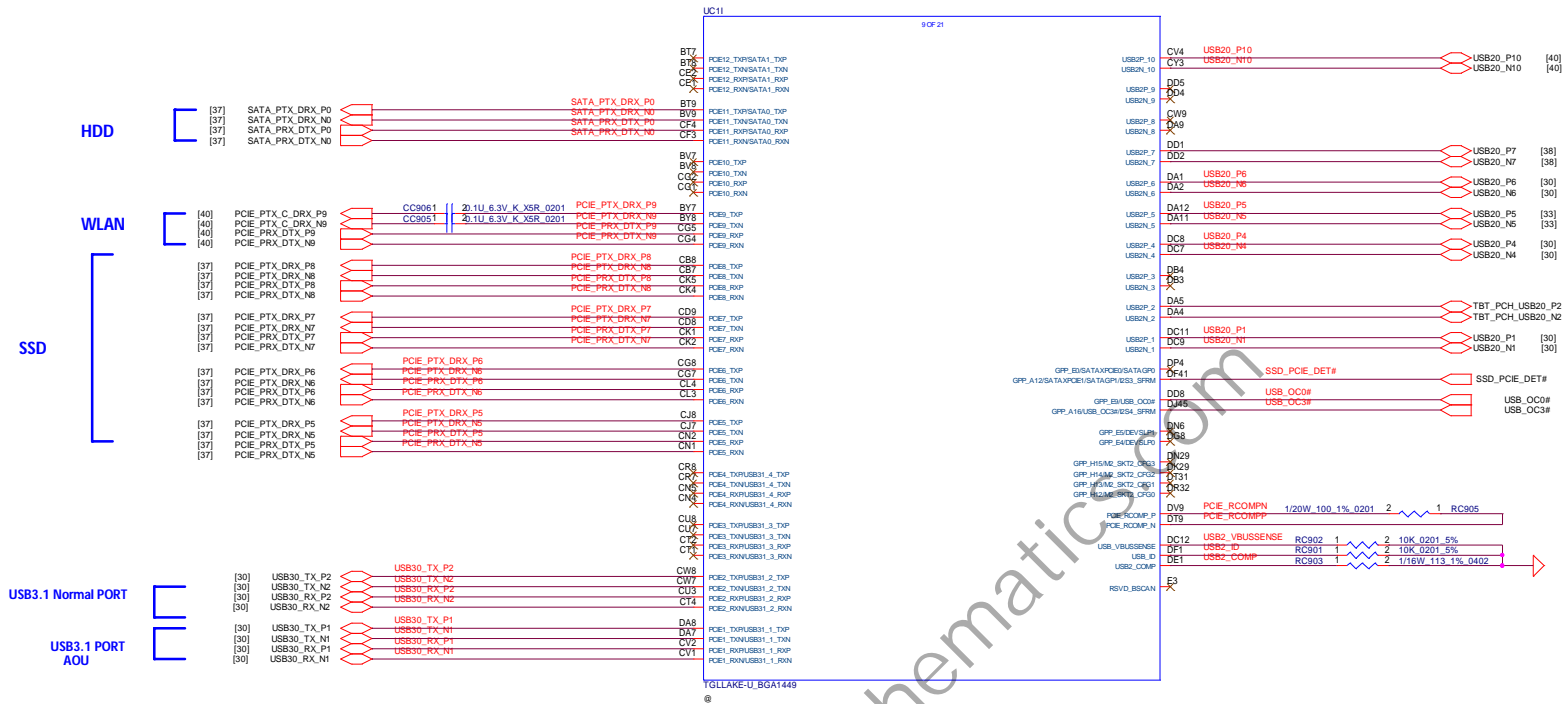
Board ID Table 1: 3.3V Level

Board ID	GPP_E1	0	Non-FPR	No Use
Board ID1		1	FPR	No Use
Board ID2	GPP_E2	0	Non-TS	No Use
		1	TS	No Use
Board ID3	GPP_E10	00	FHD	---
		01	UHD	No Use
Board ID4	GPP_E11	10	FHD HDR	---
		11	Reserved	No Use
Board ID5	GPP_E12	00	13"	No Use
		01	14"	---
Board ID6	GPP_E13	10	15"	---
		11	17"	No Use
Board ID7	GPP_E17	0	Non-TPM	No Use
		1	TPM	No Use

Board ID Table 1: 1.8V Level

Board ID8	GPP_F11 H	00	Samsung	---
		01	Micro	---
Board ID9	GPP_F12 L	10	Hynix	---
		11		No Use
Board ID10	GPP_F13 H	00	4G	No Use
		01	8G	---
Board ID11	GPP_F14 L	10	12G	---
		11	16G	---
Board ID12	GPP_F15	0	OPT	No Use
		1	UMA	
Board ID13	GPP_F16	10		Reserved for dGPU
		11		
				No Use
				Reserved for Project

BOARD ID



BT

FPR

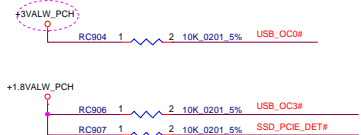
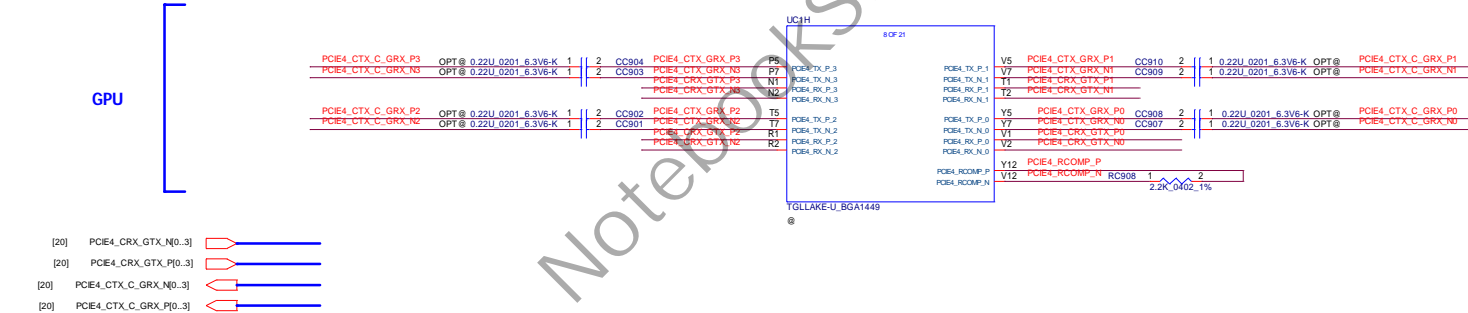
Card reader

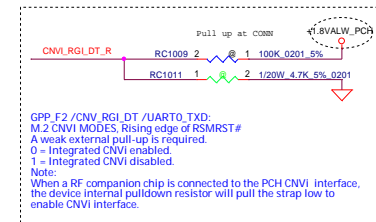
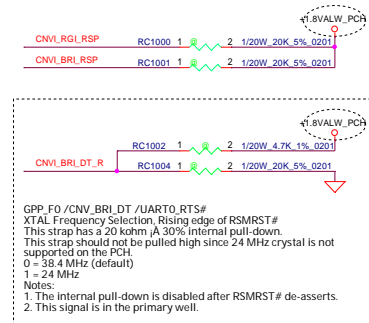
Camera

USB3.0 Normal

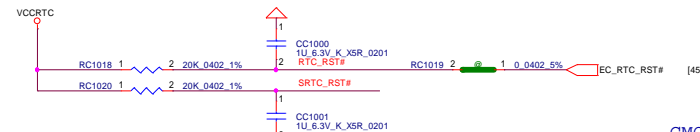
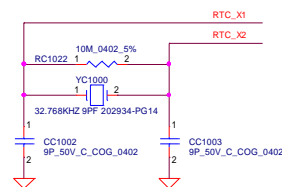
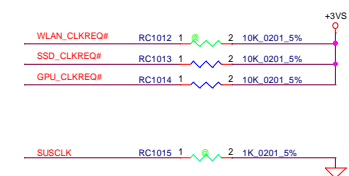
TBT

USB3.0 AOU



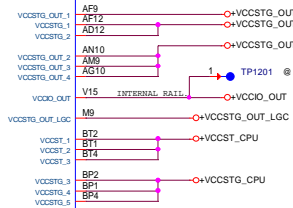
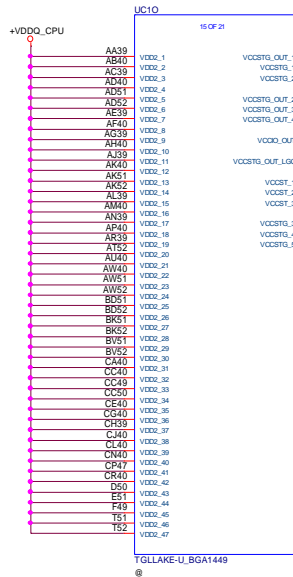
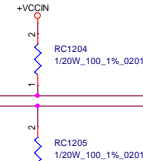
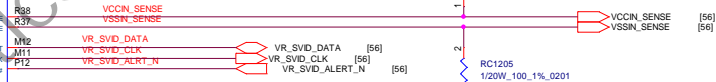
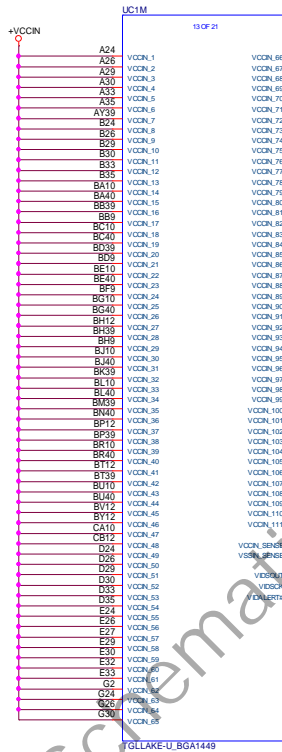
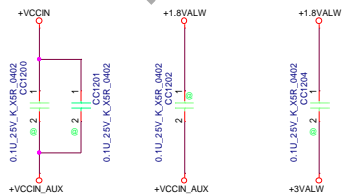
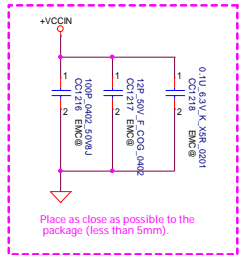
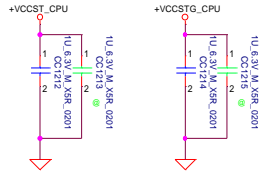
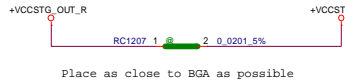
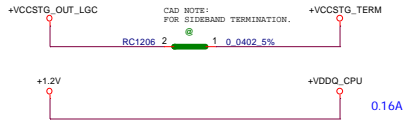
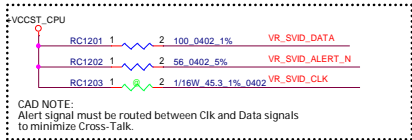


CLKOUT_PCIE_P / N [3, 0] = Support up to PCIe Gen4

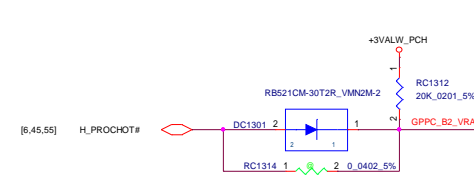
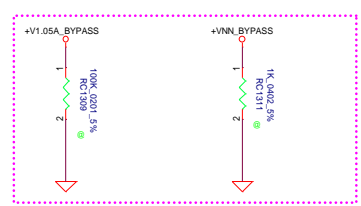
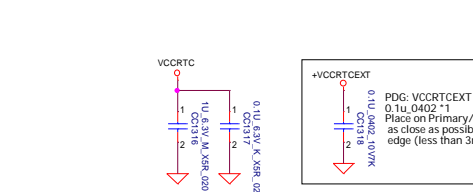
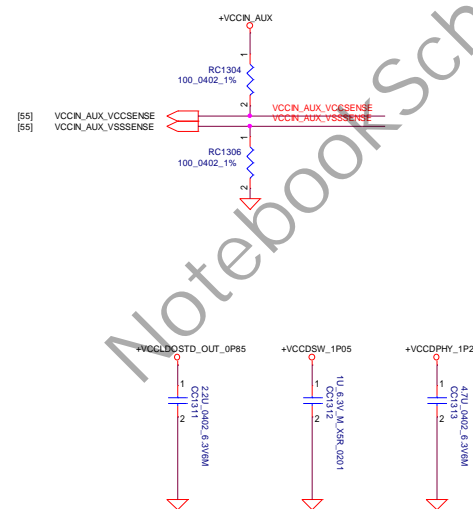
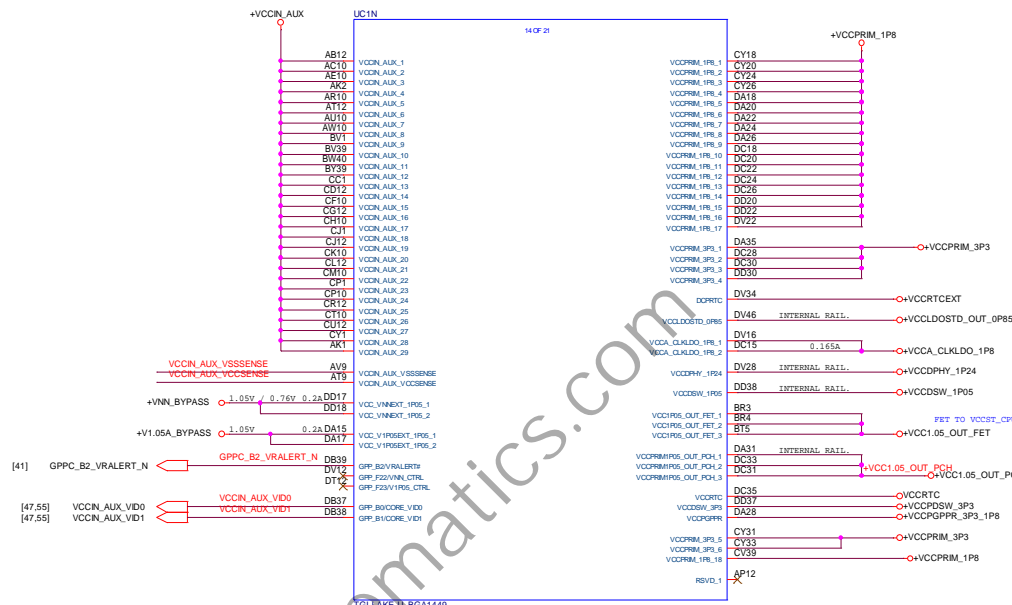
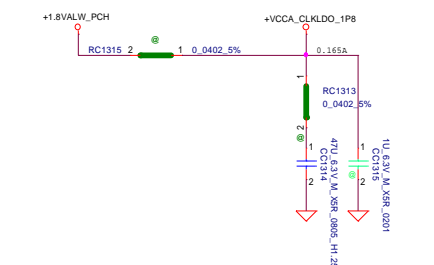
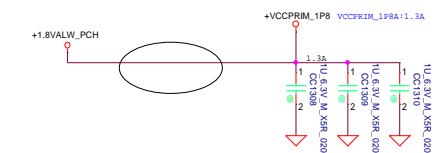
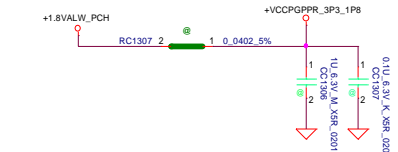
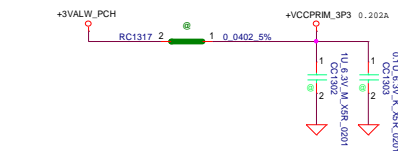
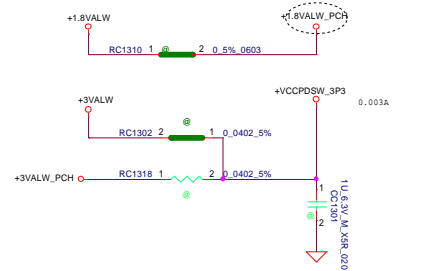


```
CMOS RESET
SAVE CMOS    = PU (Default)
CLEAR CMOS   = PD

ME RESET
SAVE ME      = PU (Default)
CLEAR ME     = PD
```

Short VCCSTG_BGA pins AF12 and AD12 with the VCCSTG_OUT_BGA pins AB10, AB5, AD10 and AF9 together on the board.



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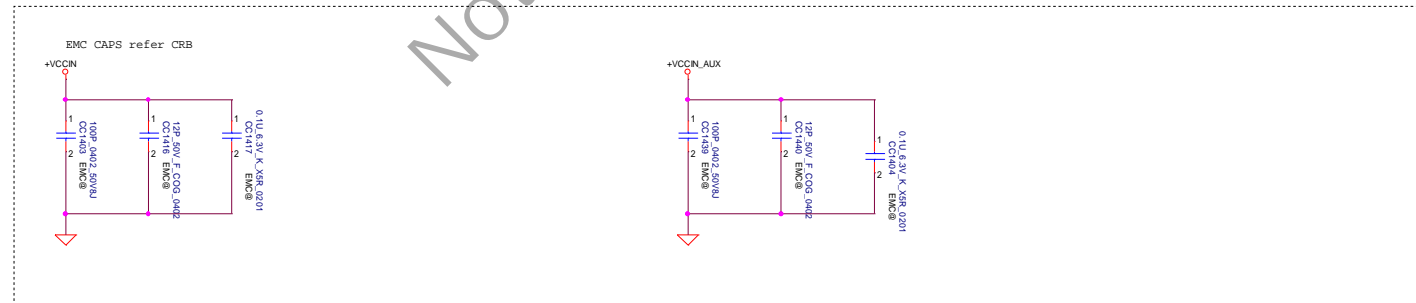
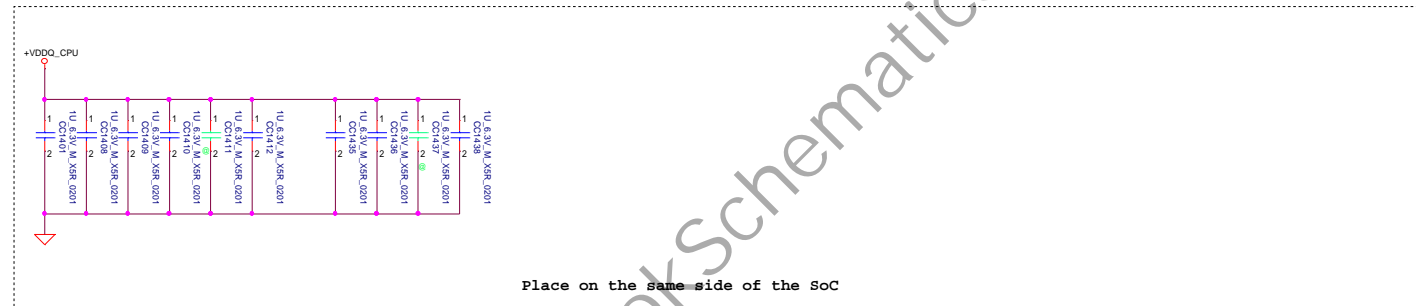
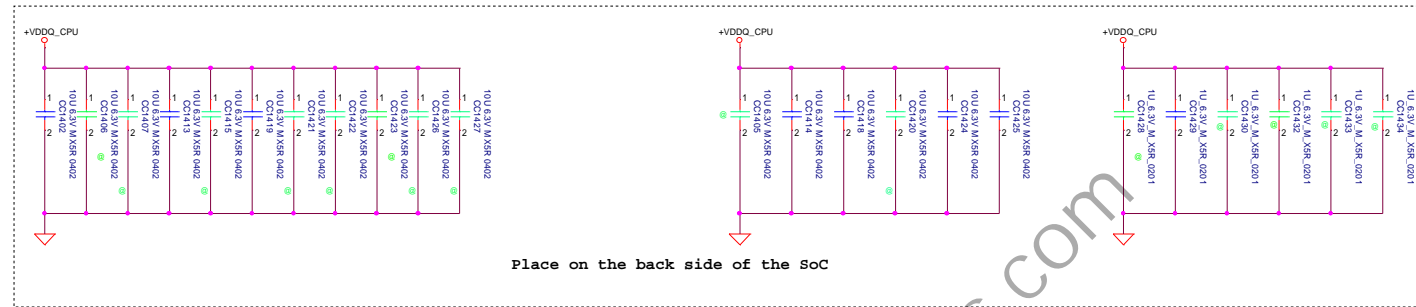
VDDQ_CPU :

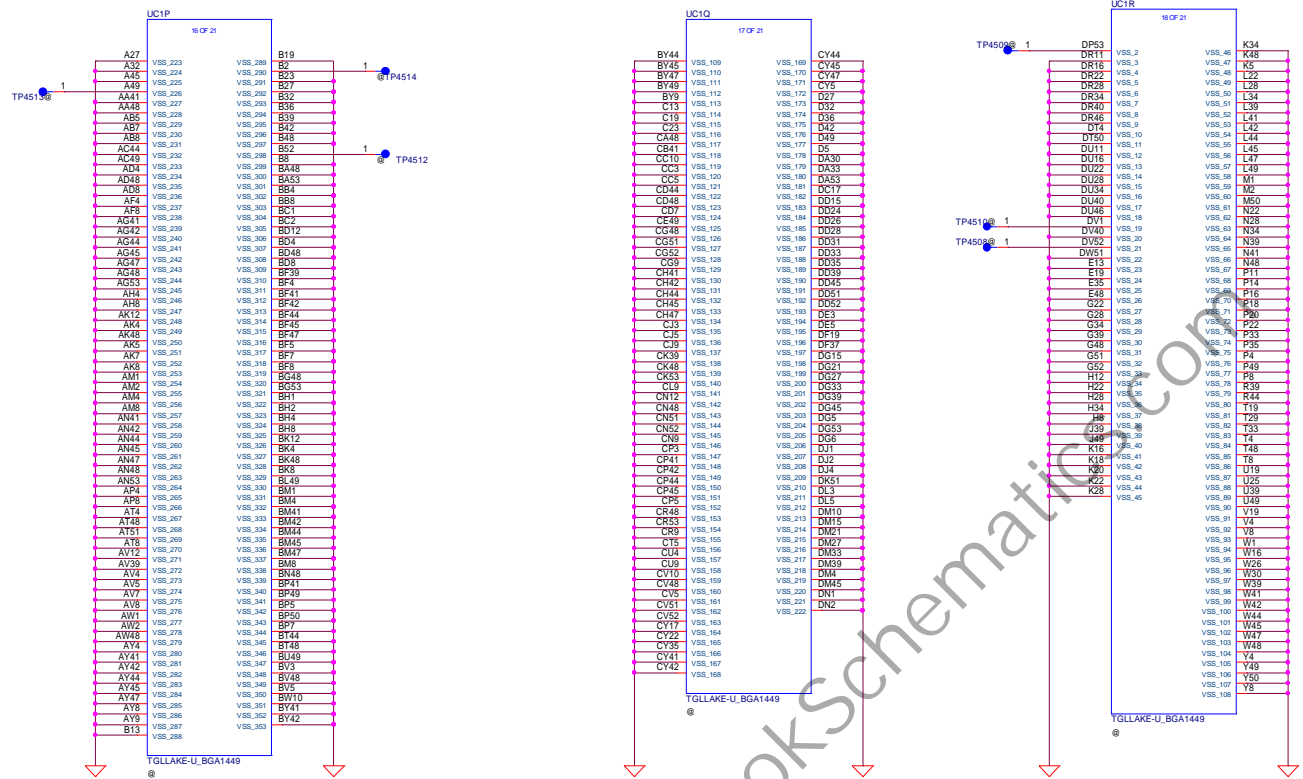
PDG:1 , 2x47uF 0603, 8x10uF 0402, 8x1uF 0402,

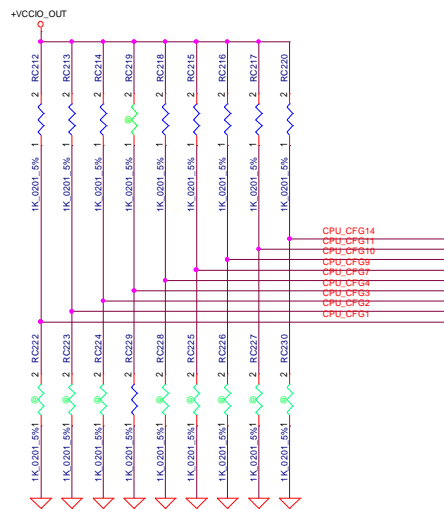
vs

C750 ITL: 6x10uF 0402, 3x1uF 0402,10x1uF 0201,Reserve 8x10uF 0402,7x1uF 0201

S550 ITL 6x10uF 0402, 9x1uF 0201 Reserve 11x10uF 0402, 7x1uF 0201





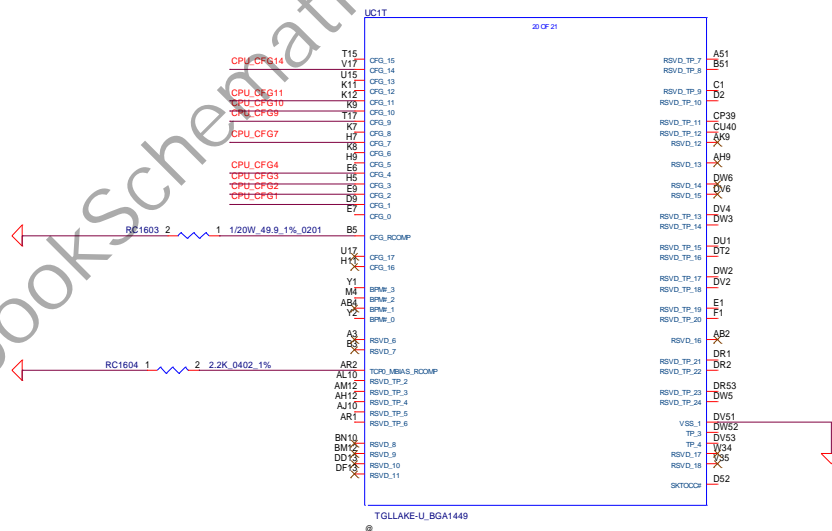
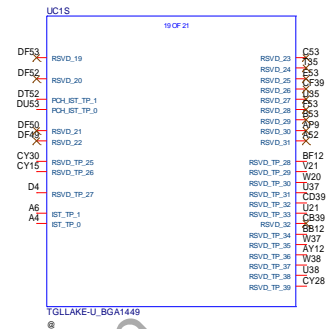


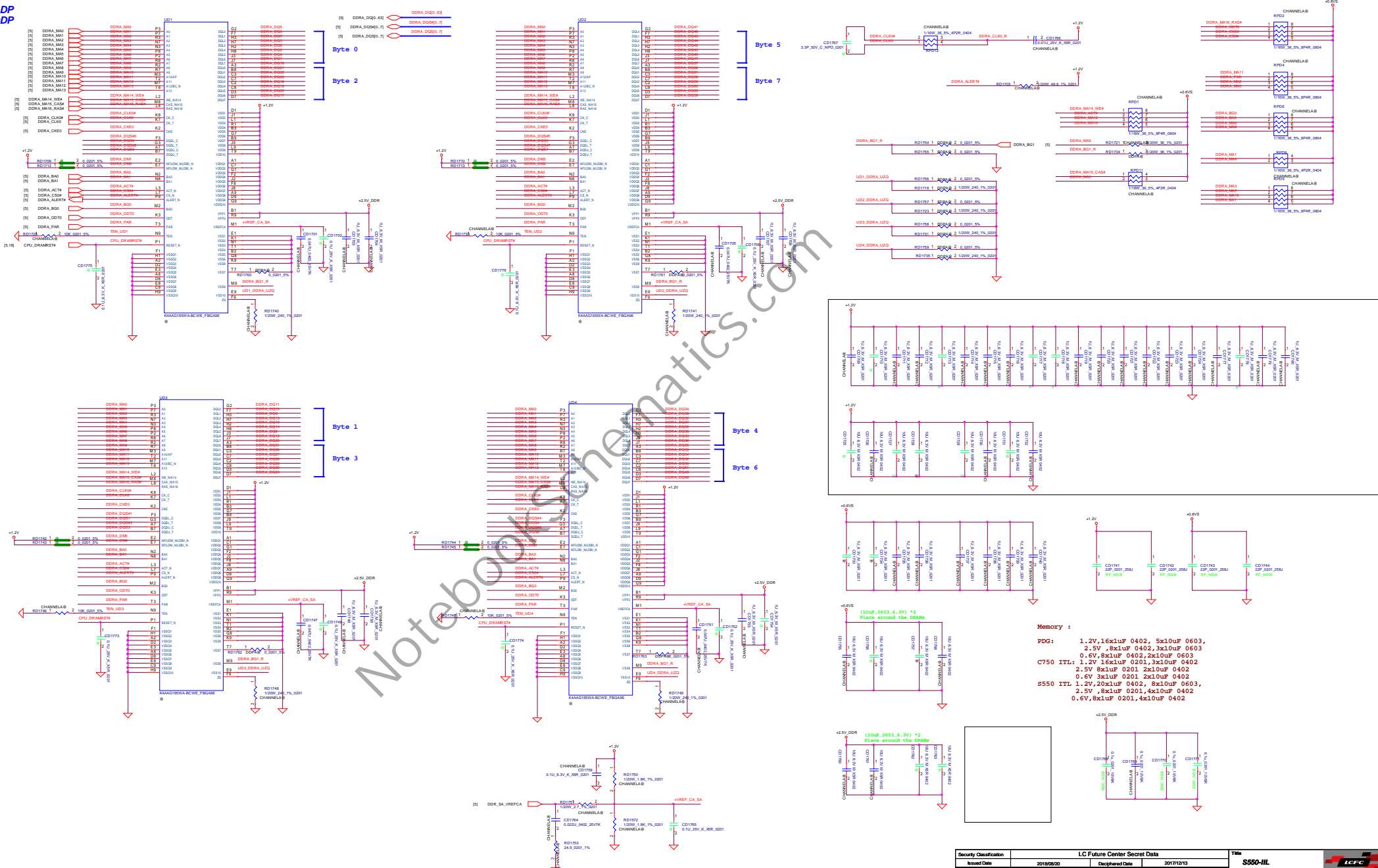
Change CFG Follow PDG, V1.0---Xukun1220

Pin Name	Strap Description	Configuration	Default Value
CFG[0]	RSVD	None	
CFG[3:1]	RSVD	Pull-up to VCCIO	1Kohm
CFG[4]	eDP enable strap 1 = Disabled 0 = Enabled	Pull-up to VCCIO / Pull-down Platform design dependent	1Kohm
CFG[6:5]	RSVD	None	
CFG[7]	PEG deferred link training 1 = (default) PEG Train immediately following RESET at de-assertion 0 = PEG Wait for BIOS for training.	Pull-up to VCCIO / Pull-down Platform design dependent	1Kohm
CFG[8]	RSVD	None	
CFG[11:9]	RSVD	Pull-up to VCCIO	1Kohm
CFG[13:12]	RSVD	None	
CFG[14]	PEG60 Lane Reversal 1 = Normal(Default) 0 = Reversed	Pull-up to VCCIO / Pull-down Platform design dependent	1Kohm
CFG[17:15]	RSVD	None	

CPU PCIe Gen4 Bifurcation and Lane Reversal Mapping

Bifurcation	CFG Signals	Lanes			
	CFG [14]	0	1	2	3
1x4	1	0	1	2	3
1x4(Reversed)	0	3	2	1	0



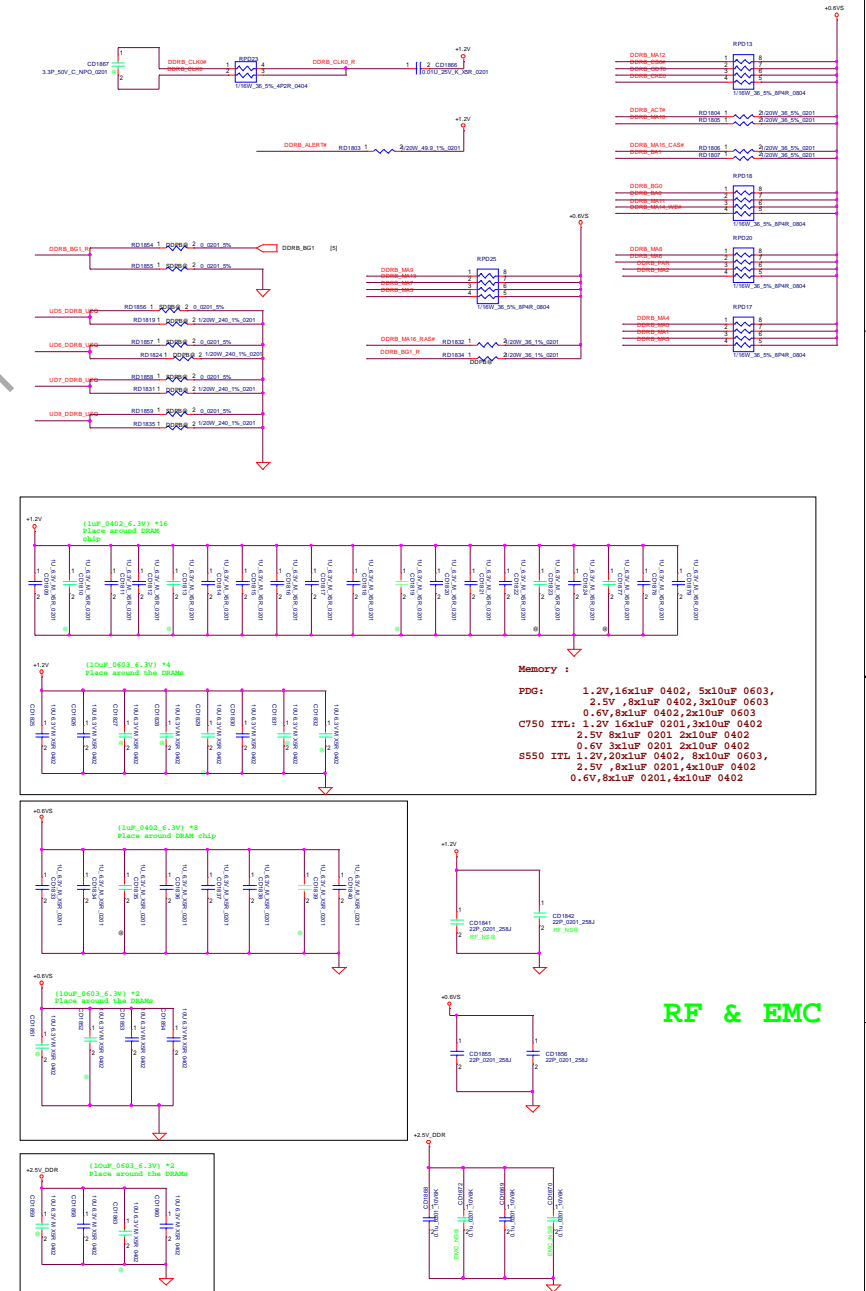
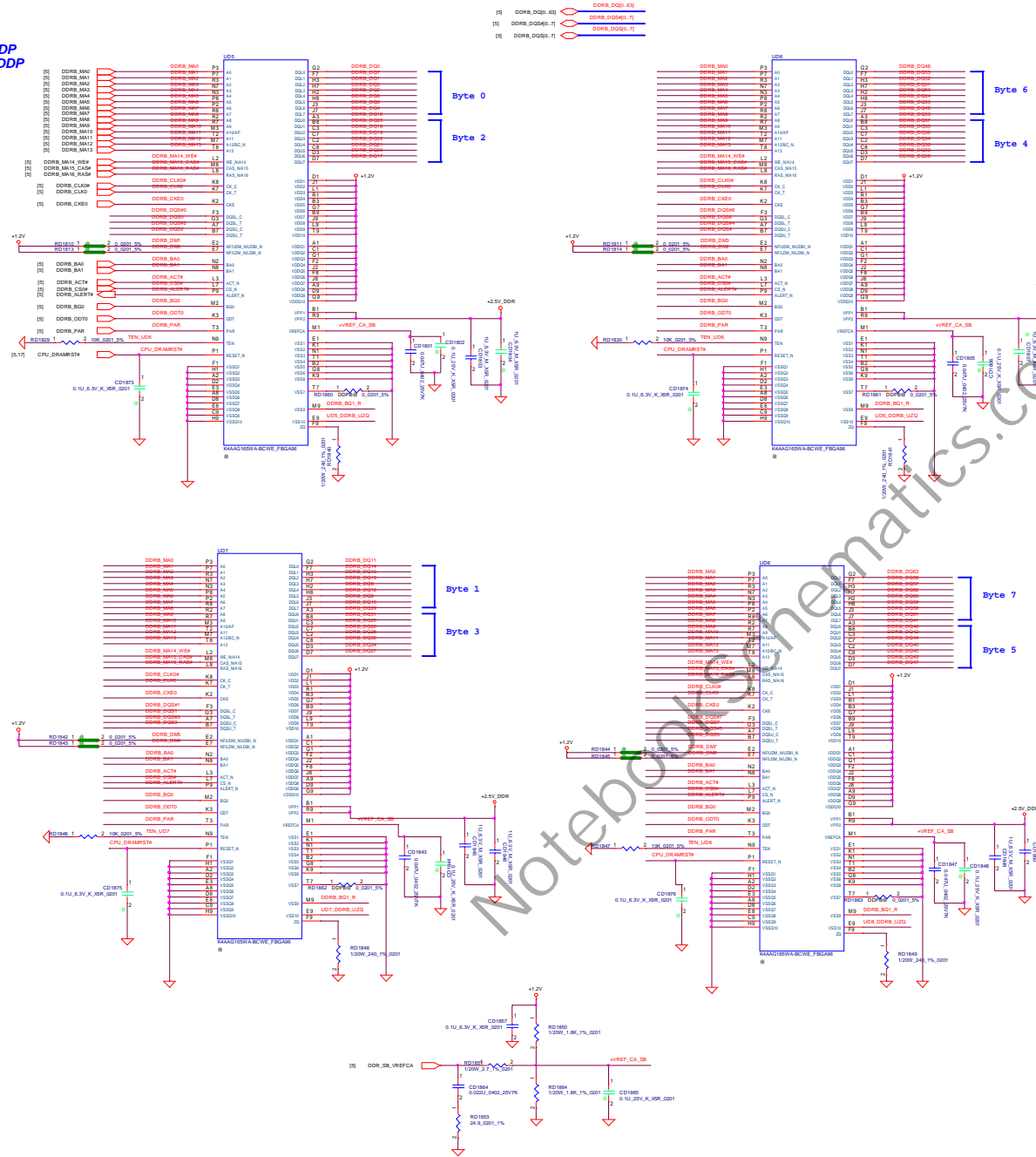


Memory :

PDG : 1.2V, 16x1uF 0402, 5x10uF 0603
2.5V, 8x1uF 0402, 3x10uF 0603
0.6V, 8x1uF 0402, 2x10uF 0603
C750 ITL: 1.2V 16x1uF 0201, 3x10uF 0402
2.5V 8x1uF 0201, 2x10uF 0402
0.6V 3x1uF 0201, 2x10uF 0402
S550 ITL: 1.2V, 20x1uF 0402, 8x10uF 0603,
2.5V, 8x1uF 0201, 4x10uF 0402
0.6V, 8x1uF 0201, 4x10uF 0402

Security Classification		LC Future Center Secret Data		Title	
Issued Date	2019/08/29	Designed Date	2017/12/13	Rev	S550-JL
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				Rev	01

8Gb SDP
16Gb DDP



RF & EMC

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Issued Date		Designated Date		S550-JL	
2016/08/29		2016/08/29			
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				Memory Channel B	

GPIOs

GPIO	I/O	ACTIVE	Function Description
GPIO0	OUT	-	GPU Core VDD PWM control signal
GPIO1	OUT	N/A	FB Enable for GC6 2.0
GPIO2	OUT	N/A	GPU EVENT
GPIO3	OUT	N/A	
GPIO4	OUT	N/A	1.8VGS_PWR_EN_R FOR 1.8VGS&1.0VGS&NVDD
GPIO5	OUT	N/A	
GPIO6	OUT	-	PSI_VGA
GPIO7	OUT	N/A	
GPIO8	OUT	-	VRAM_VDDQ_ADJ control the power voltage
GPIO9	I/O	N/A	10K Pull-up
GPIO10	OUT		FBVREF_ALTV for GDDR6
GPIO11	OUT	-	
GPIO12	IN		AC Power Detect Input (10K pull High)
GPIO13	OUT	-	
GPIO14	IN	N/A	
GPIO15	IN	N/A	
GPIO16		N/A	
GPIO17	IN	N/A	
GPIO18	OUT	N/A	GPIO18_FP_FUSE
GPIO19	IN	N/A	
GPIO20		N/A	
GPIO21	OUT		
OVERT	OUT		Active Low Thermal Catastrophic Over Temperature

GDDR6 Mapping table

DRAM1(0...31)			DRAM2(32...63)		
	CHA(Byte# 0,1)	CHB(Byte# 2,3)	CHA(Byte# 4,5)	CHB(Byte# 4,5)	Remark
CMD0	CA0_A				
CMD9	CA1_A				
CMD8	CA2_A				
CMD12	CA3_A				
CMD4		CA0_B			
CMD12		CA1_B			
CMD5		CA2_B			
CMD13		CA3_B			
CMD7	CA4_A	CA4_B			
CMD11	CA5_A	CA5_B			
CMD15	CA6_A	CA6_B			
CMD14	CA7_A	CA7_B			
CMD3	CAS_A	CAS_B			
CMD1	CA9_A	CA9_B			
CMD6	CAB_A	CAB_B			
CMD10	CKE_A	CKE_B			10K Pull 1.25VGS
CMD2	REST	REST			10K Pull GND
CMD20			CA0_A		
CMD28			CA1_A		
CMD21			CA2_A		
CMD29			CA3_A		
CMD16				CA0_B	
CMD25				CA1_B	
CMD24				CA2_B	
CMD33				CA3_B	
CMD23			CA4_A	CA4_B	
CMD27			CA5_A	CA5_B	
CMD30			CA6_A	CA6_B	
CMD31			CA7_A	CA7_B	
CMD19			CA8_A	CAB_B	
CMD17			CA9_A	CAB_B	
CMD22			CAB_A	CAB_B	
CMD26			CKE_A	CKE_B	10K Pull 1.25VGS
CMD18			REST	REST	10K Pull GND
CMD35					NC

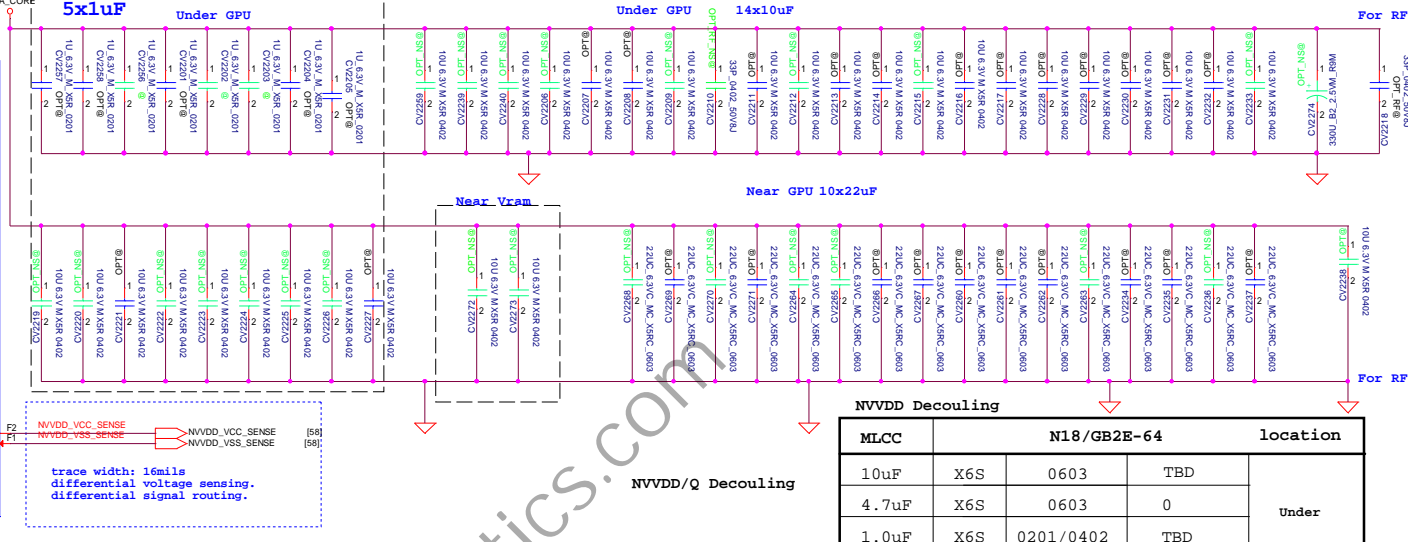
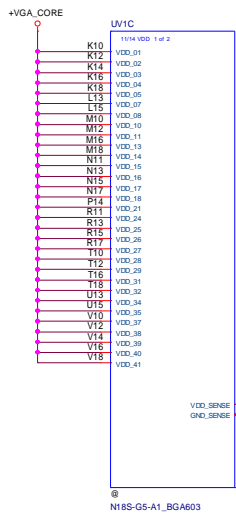
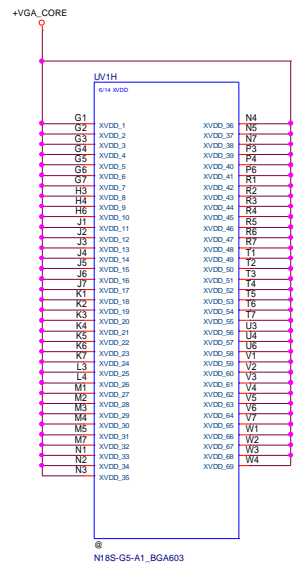
Performance Mode P0 TDP and EDP-Continuous current (GDDR5)

Product	TDP		Min Core Clk	EDP									
	GPU	Mem		NVVDD		GPU FBIO (1.35V)		FB Total (GPU+Mem) (1.35V)		1.0V Total (1.0V@N17s) (1.05V@N16s)		1.8V/3.3V Total 1.8V N17s 3.3V N16s	
(W)	(W)	(MHz)	Cont. (A)	Peak (A)	Cont. (A)	Peak (A)	Cont. (A)	Peak (A)	Cont. (A)	Peak (A)	Cont. (A)	Peak (A)	
N16S-GMR	16	1.6	849	19	34	2.0	2.9	4.2	6.8	0.8	2.1	---	0.06
N16S-GTR	18	1.7	965	26.5	53	2.0	2.9	4.2	6.8	0.8	2.1	---	0.06
N17S-LG(0x1D12)	10	1.6	936	15.4	48.3	2.5	2.8	5.0	5.8	0.1	0.2	0.2	---
N17S-LG(0x1D52)	10.5	1.7	936	15.6	48.6	2.7	3.0	5.3	6.2	0.1	0.2	0.2	---
N17S-G1	25	1.9	1468	30.0	60.1	3.0	3.4	5.6	6.9	0.1	0.2	0.3	---
N17S-G0	25	1.9	1518	27.8	42.0	3.2	3.9	5.8	7.4	0.2	0.3	0.5	---
N17S-G2	25	1.9	1518	28.6	60.3	3.2	3.9	5.8	7.4	0.2	0.3	0.5	---

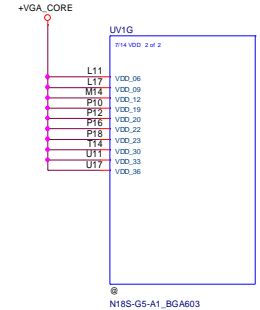
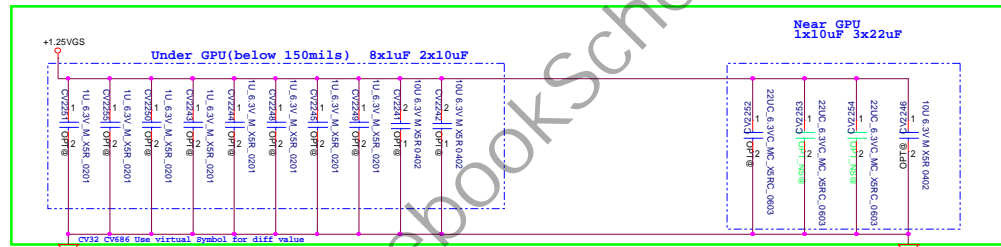
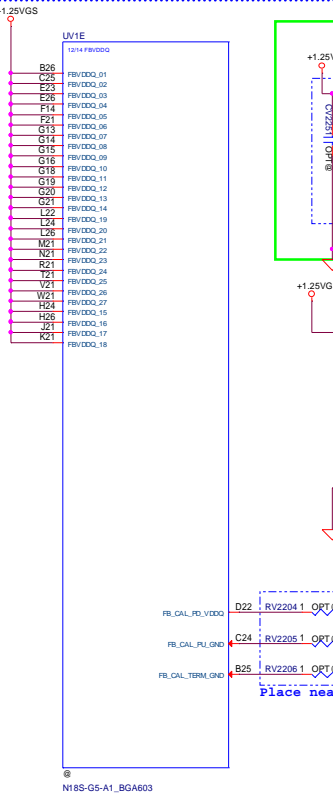
POWER RAIL

FB_PLL_AVDD	Frame Buffer PLL analog Power Rail	1.8V
GPCPLL_AVDD	Core PLL analog Power Rails	1.8V
SP_PLLVDD	Core Clock PLL Analog Power Rail	1.8V
VDD,VDDS	Primary Core Power Rail	NVVDD
VDD_SENSE		
GND_SENSE		
VDDS_SENSE		
GNDS_SENSE		
VDD18 or 1V8_MAIN	1.8V Power Rail	1.8V
1V8_AON		
VID_PLLVDD	Thermal Controller and Video Pixel Clock PLL	1.8V
	Analog Power Rail	
XS_PLLVDD	Core PLL analog Power Rails	1.8V

Product	TDP			
N18S-G5/GDDR6	25W			



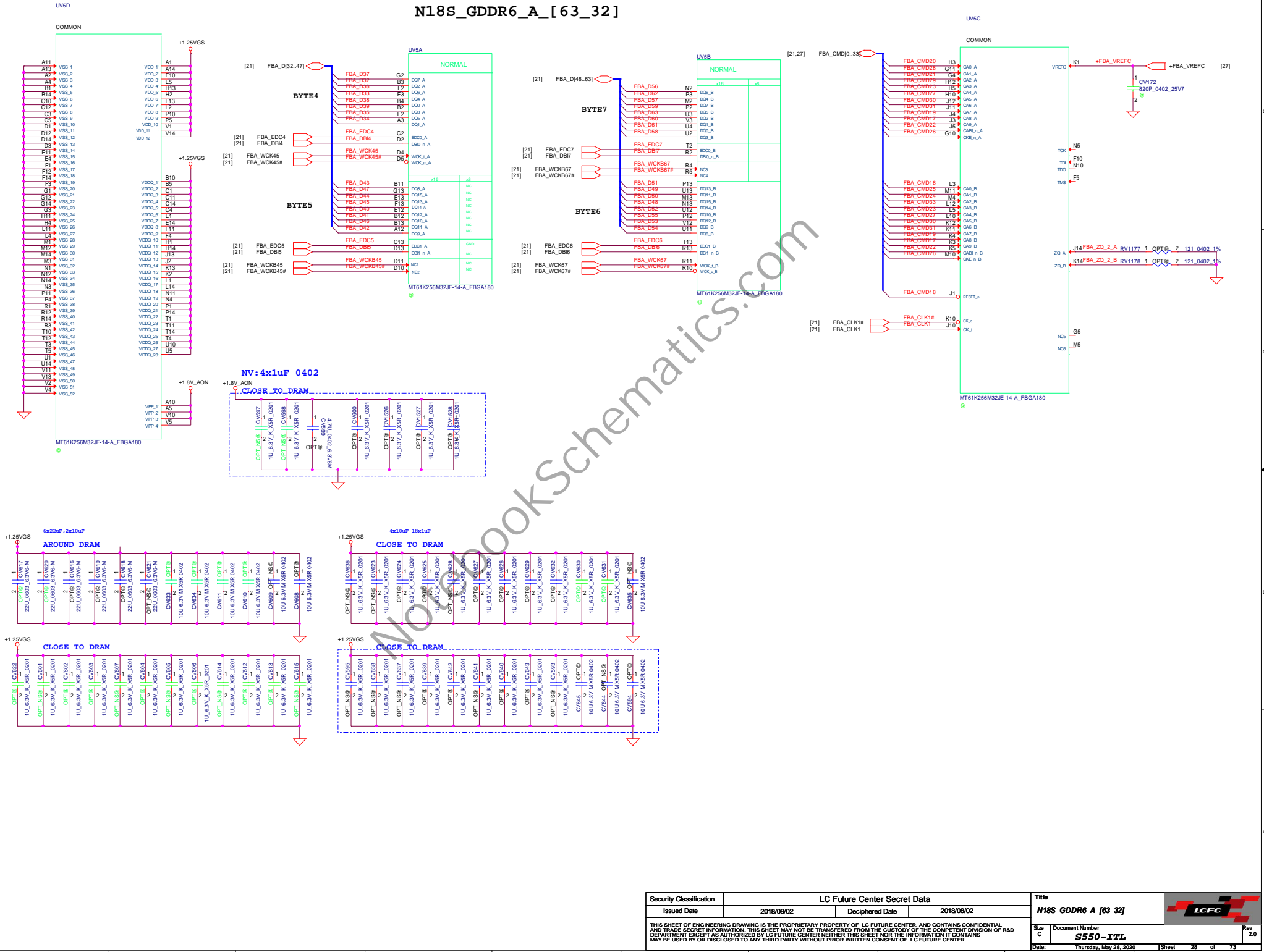
NVDD Decoupling		N18/GB2E-64		location	
MLCC					
10uF	X6S	0603	TBD	Under	
4.7uF	X6S	0603	0		
1.0uF	X6S	0201/0402	TBD		
0.47uF	X6S	0201/0402	0		
10uF	X6S	0603	0	Near	
22uF	X6S	0805	TBD		
4.7uF	X6S	0603	0		
470uF	POS	7343	TBD		

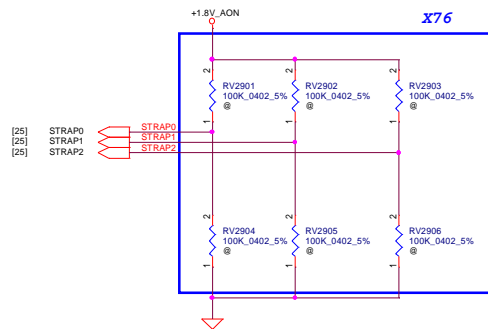


CALIBRATION PIN	GDDR6
FB_CAL_x_PD_VDDQ	40.2Ohm
FB_CAL_x_PU_GND	40.2Ohm
FB_CAL_x_TERM_GND	40.2Ohm

FBVDDQ Decoupling		N18/GB2E-64		location	
MLCC					
0.47uF	X6S	0201	24	Under	
1.0uF	X6S	0201/0402	0		
10uF	X6S	0603	4		
10uF	X6S	0603	2		
22uF	X6S	0603	5	Near	

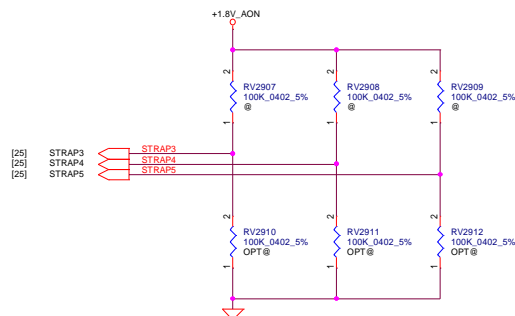
N18S_GDDR6_A [63_32]





VRAMCFG

GPU VRAM	FB Memory (GDDR6)		Starp	STRAP2	STRAP1	STRAP0
2GB	Samsung 8Gb	K4Z80325BC-HC14	0x0	L	L	L
	Micron 8Gb	MT61K256M32JE-14:A	0x1	L	L	H



STRAP5	STRAP4	STRAP3	SMB_ALT_ADDR	DEVID_SEL	PCIE_CFG	VGA_DEVICE
L	L	L	0	0	0	0

1: SMB_ALT_ADDR ENABLE

0: SMB_ALT_ADDR DISABLE

1: DEVID_SEL REBRAND

0: DEVID_SEL ORIGINAL

1: PCIE_CFG LOW POWER

0: PCIE_CFG HIGH POWER

1: VGA_DEVICE ENABLE

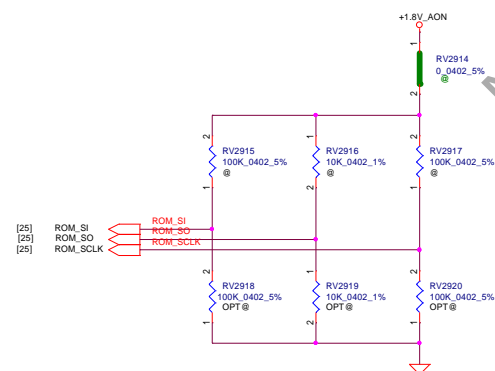
0: VGA_DEVICE DISABLE

SMB_ALT_ADDR	
0	Single GPU configurations
1	Dual GPU configurations

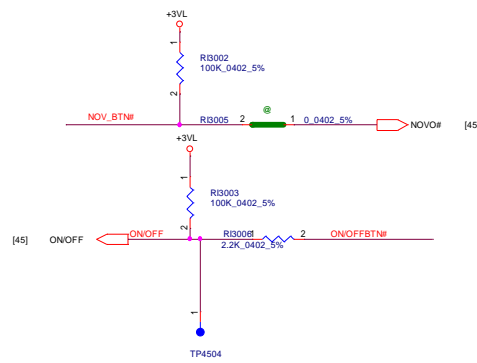
DEVID_SEL	
0	Original PCIE DEVID
1	Alternate "re-band" DEVID

PCIE_CFG	
0	(Default)
1	

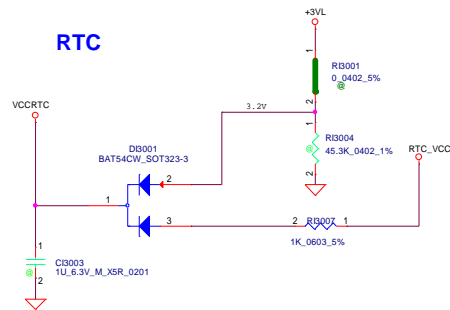
VGA_DEVICE	
0	3D Device (Class Code 302)
1	3D Device (Class Code 300)



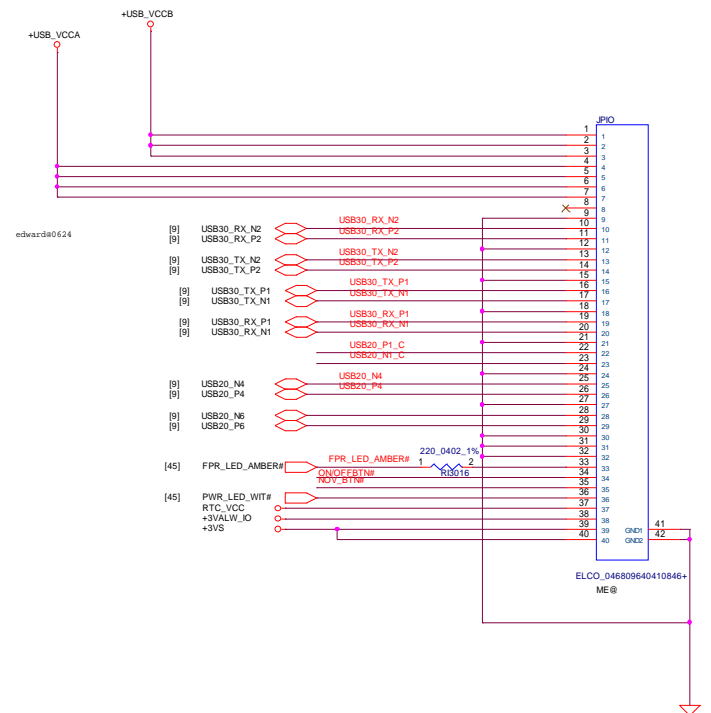
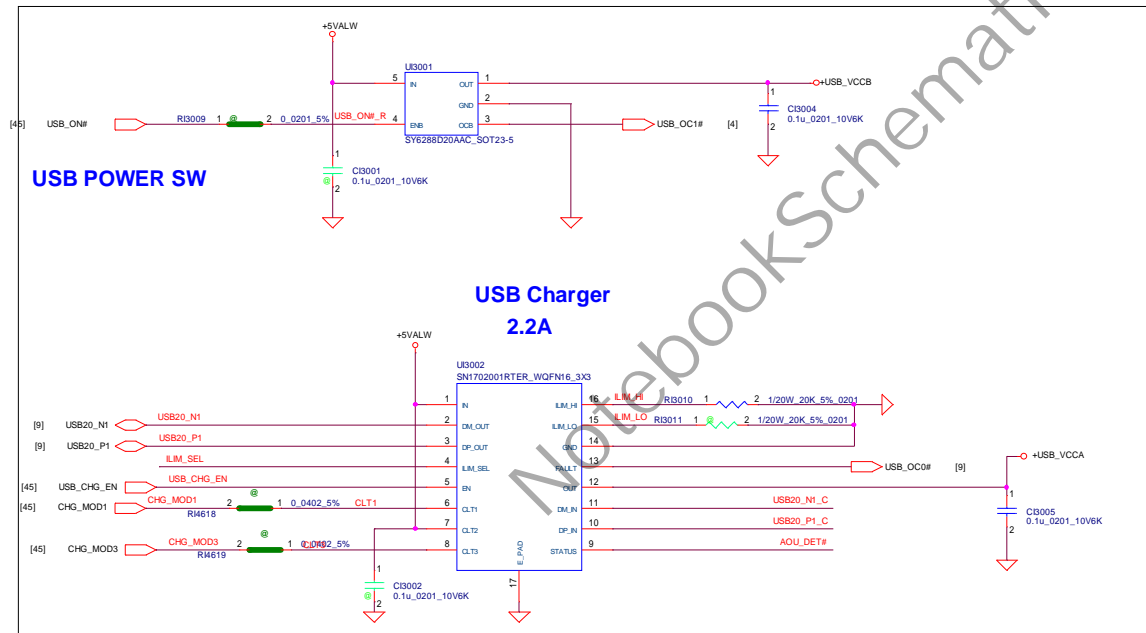
	ROM_SO	ROM_SI	ROM_SCLK	FS_OVERT*Function
N18S-G5	L	L	L	FS_OVERT*function ENABLE



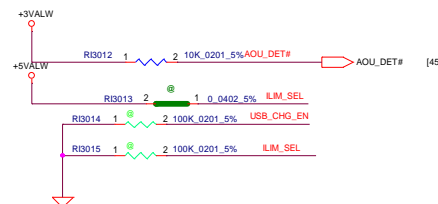
RTC

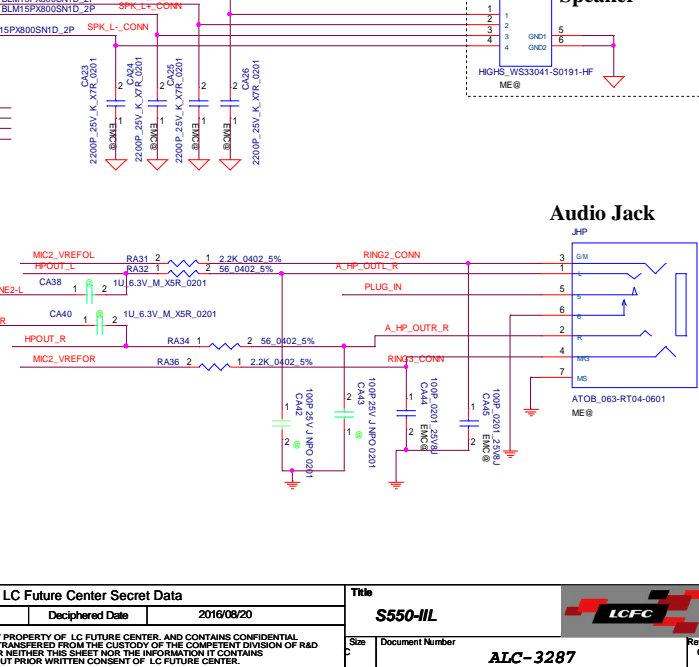
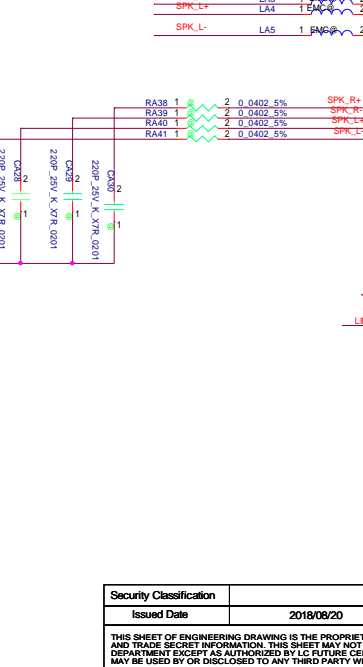
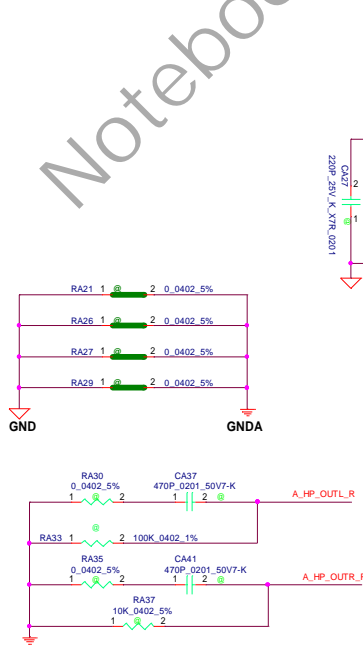
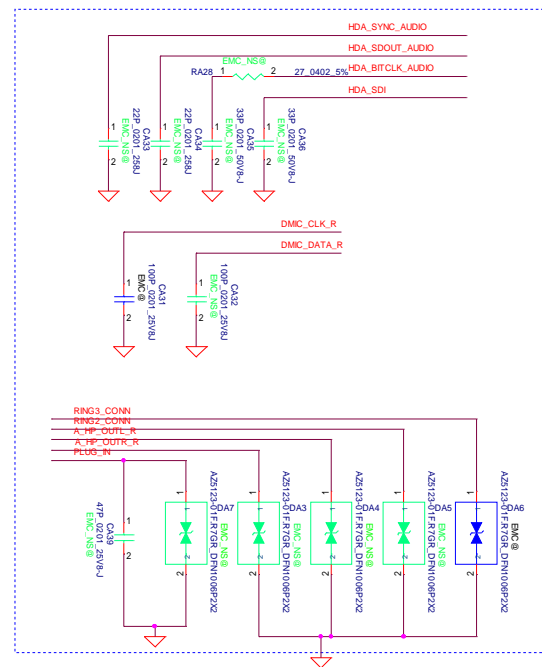
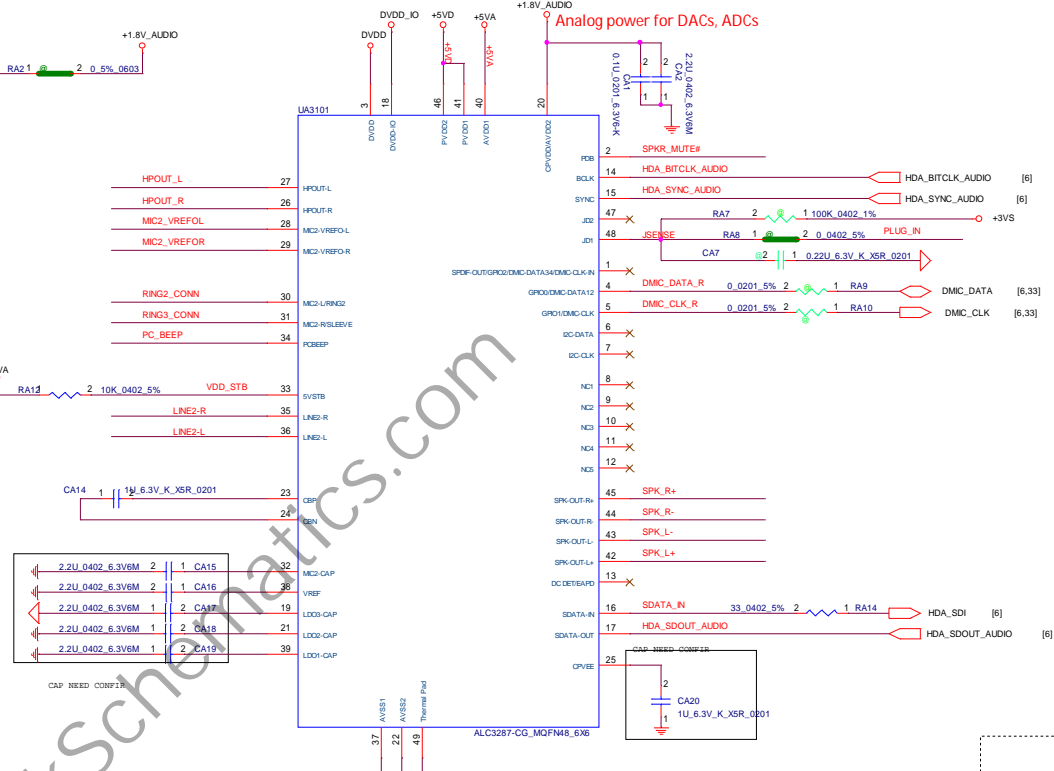
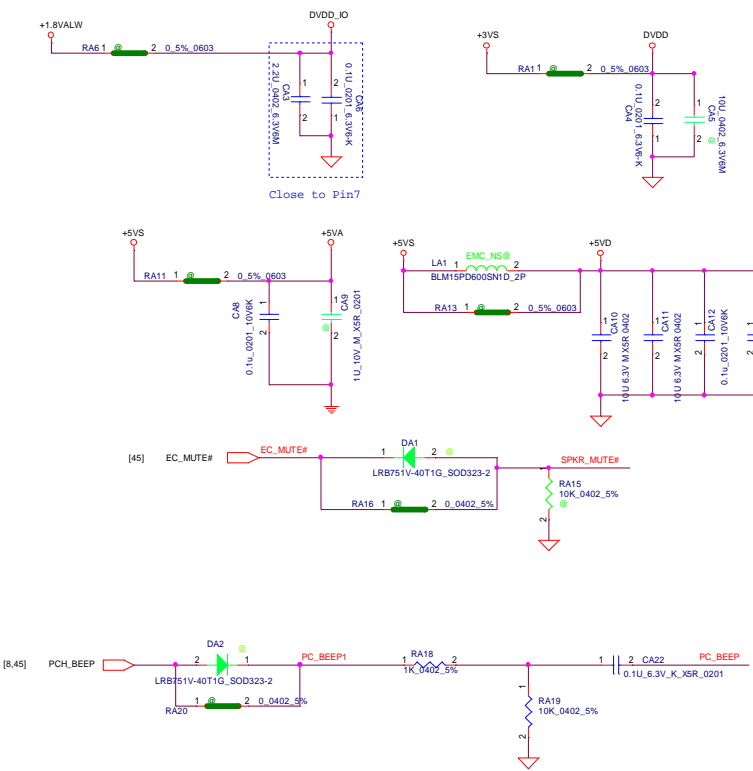


BUTTON




CLT1	CLT2	CLT3	ILIM_SEL	MOD
0	0	0	X	DCH OUT held low
1	1	1	1	CDP Data Connected and Load Detect Active
1	1	1	0	SDP2 Data Connected
1	1	0	X	SDP1 Data Connected
0	1	0	X	SDP1 Data Connected
1	0	0	X	DCP_Short Device Forced to stay in DCP BC 1.2 charging mode
1	0	1	X	DCP_Divider Device Forced to stay in DCP Divider 1 Charging Mode
0	1	1	X	DCP_Auto Data Disconnected and Load Detect Active
0	0	1	X	DCP_Auto Data Disconnected and Load Detect Active





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					Sheet 32 of 61		

[illegible]

Ton=5.5ns @5V
Toff=35ns @5V
400K spec=300ns

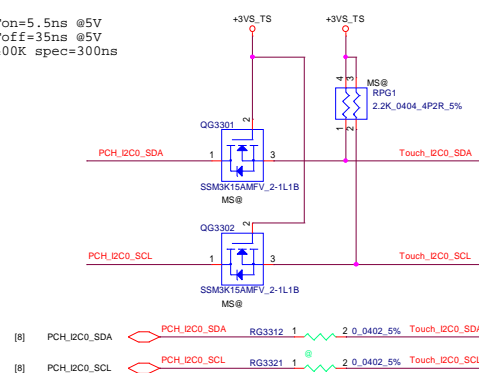
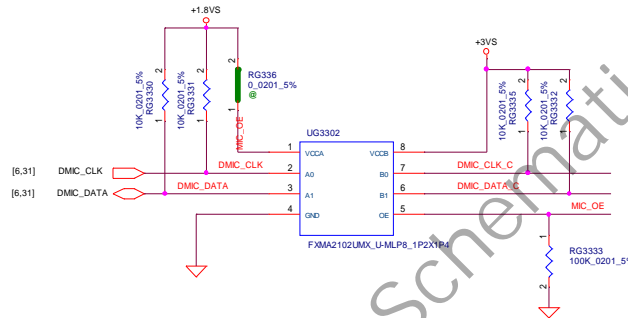


Diagram illustrating the power board connection for the camera module. The board includes a +3VS pin connected to a red wire labeled RG3307 1, which passes through a green capacitor CG3314 (0.1uF, 6.3V, XSR, 0201) to a red wire labeled FG3302 2. The camera module side features a +3VS, CAMERA pin connected to a red wire labeled CG3315 1, which passes through a blue capacitor CG3302 (1A, 32V, ERBRD00X) to a red wire labeled FG3302 2. The two red wires are connected to each other. A note 'W=40mils' is present. The bottom of the diagram shows a +3VSD pin connected to a red wire labeled RG3320 2, which goes through a green capacitor CG3320 (0.1uF, 6.3V, XSR, 0201) to a red wire labeled DMC_PWR.



Camera

RG3306 2 1 0 0402_5%

LG3302EMC_NS @

4 3

1 2

EXC24CH800U_4P

RG3308 2 1 0 0402_5%

USB20_N5

USB20_P5

USB20_N CAMERA

USB20_P CAMERA

[illegible]

TS DISCHARGER

3V3_TS

RG3326
100_0402_5%

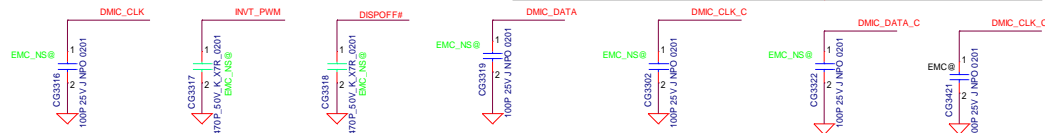
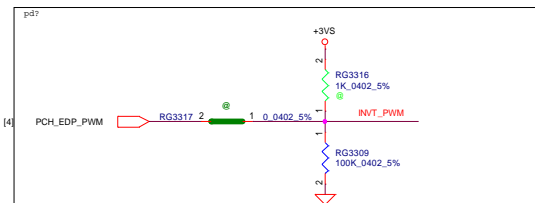
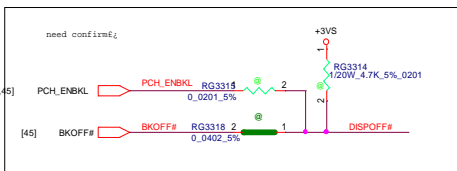
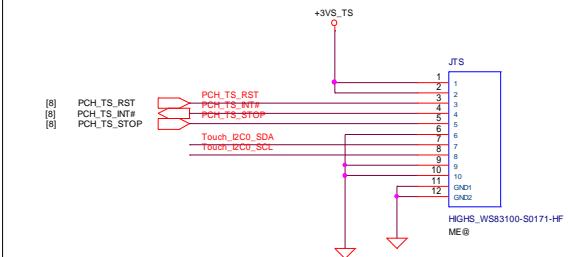
QG3305


MS@

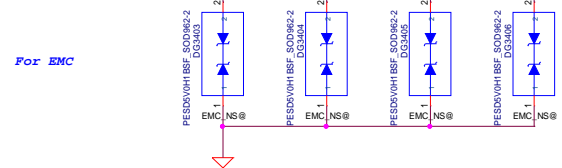
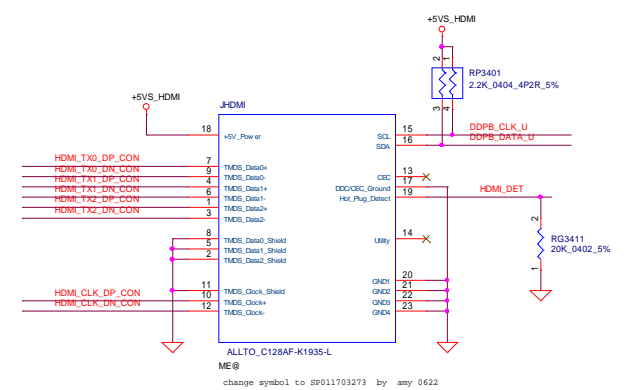
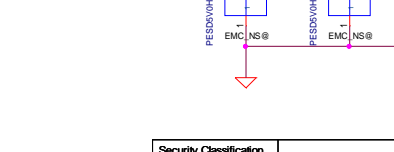
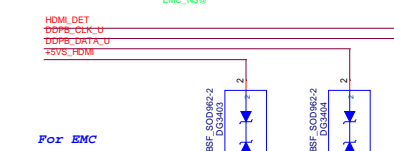
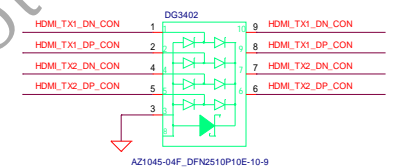
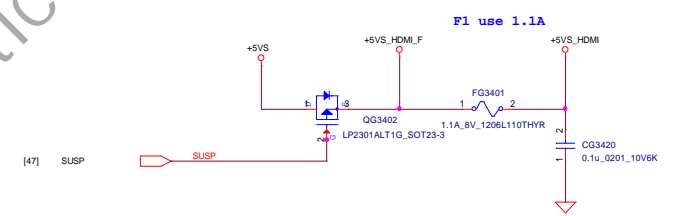
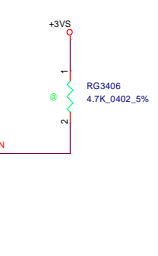
VCC_TS_ON

SSAM3K15AMFV_2-1L1B

MS@



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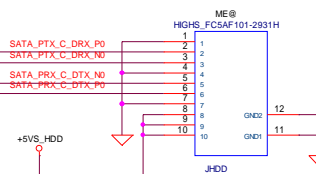
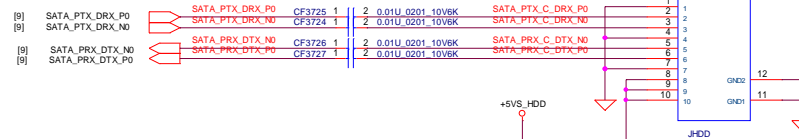
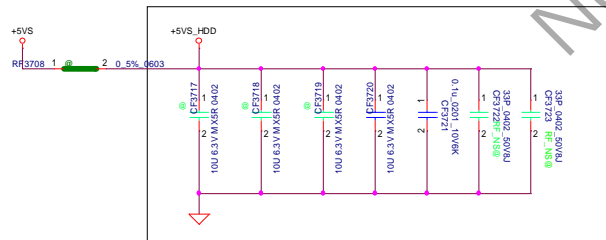
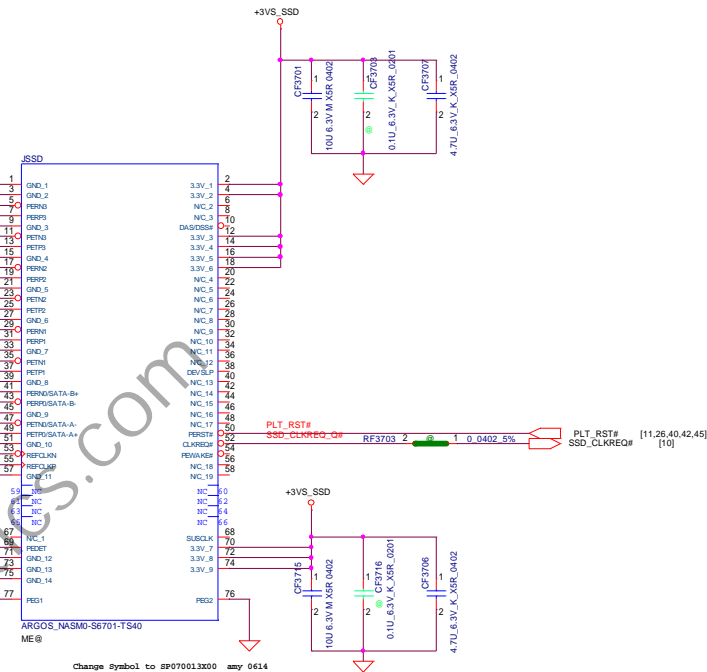
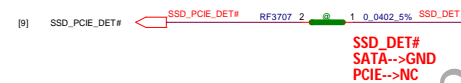
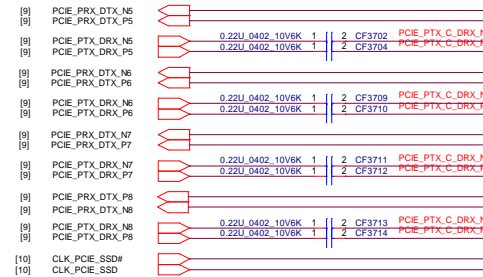
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<small>Date:</small> Thursday, May 28, 2020				<small>Sheet</small> 35	<small>of</small> 61

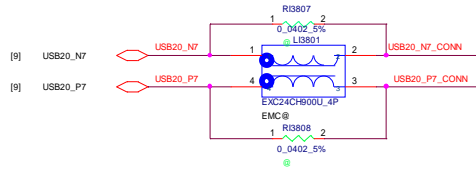
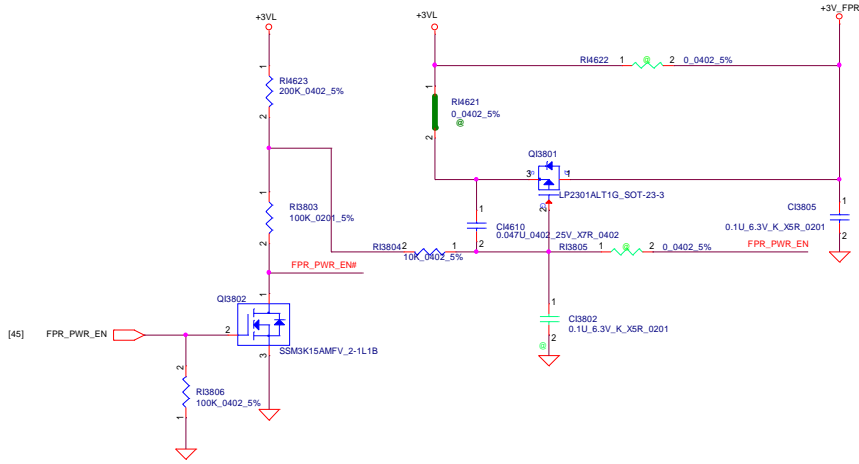


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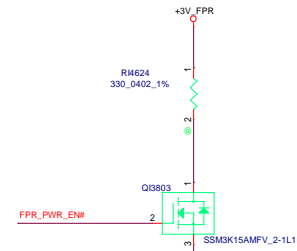
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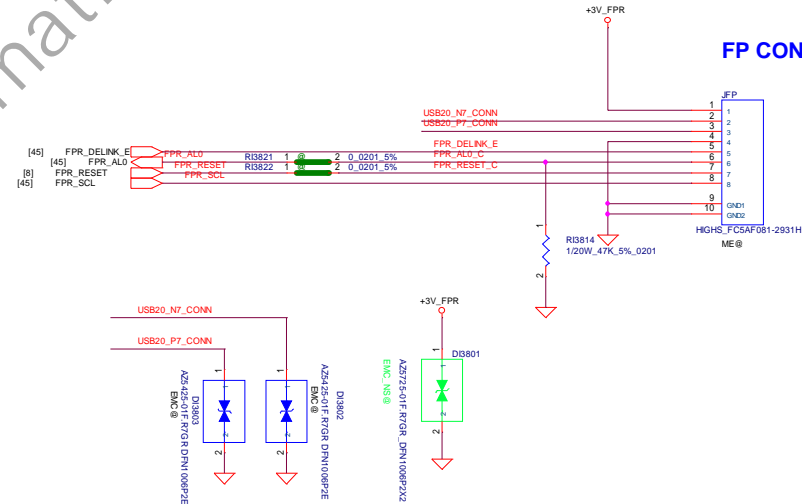
FPR POWER



FPR POWER DISCHAGER

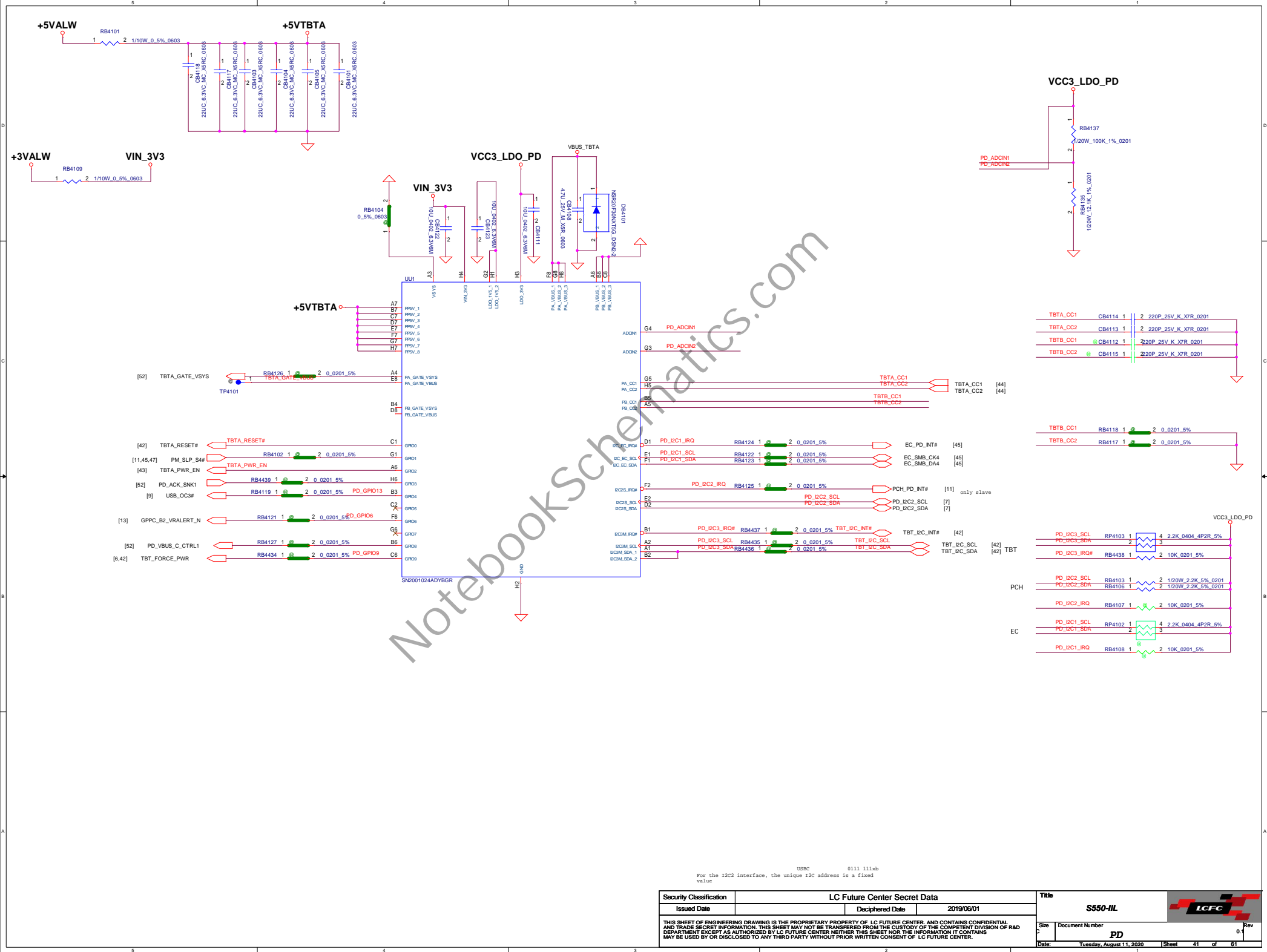


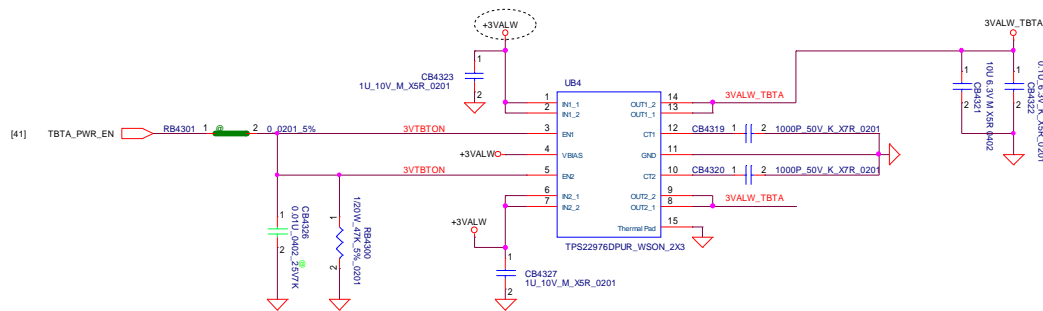
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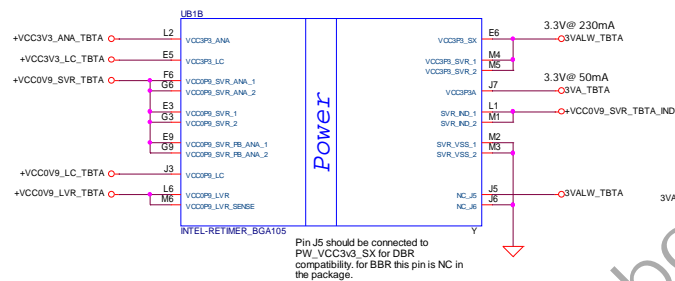
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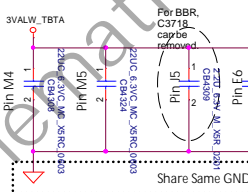




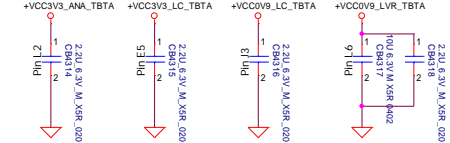
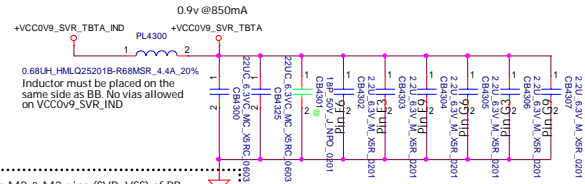
PW_VCC3v3_SX(=3VALW_TBTA) Tolerance (+ 5%/-7.5%):
Burnside Bridge power pins which connected to PW_VCC3v3_SX
should be 3.45v maximum and 3.07v minimum for normal operation.
PW_VCC3v3_SX ripple: 40mVp-p

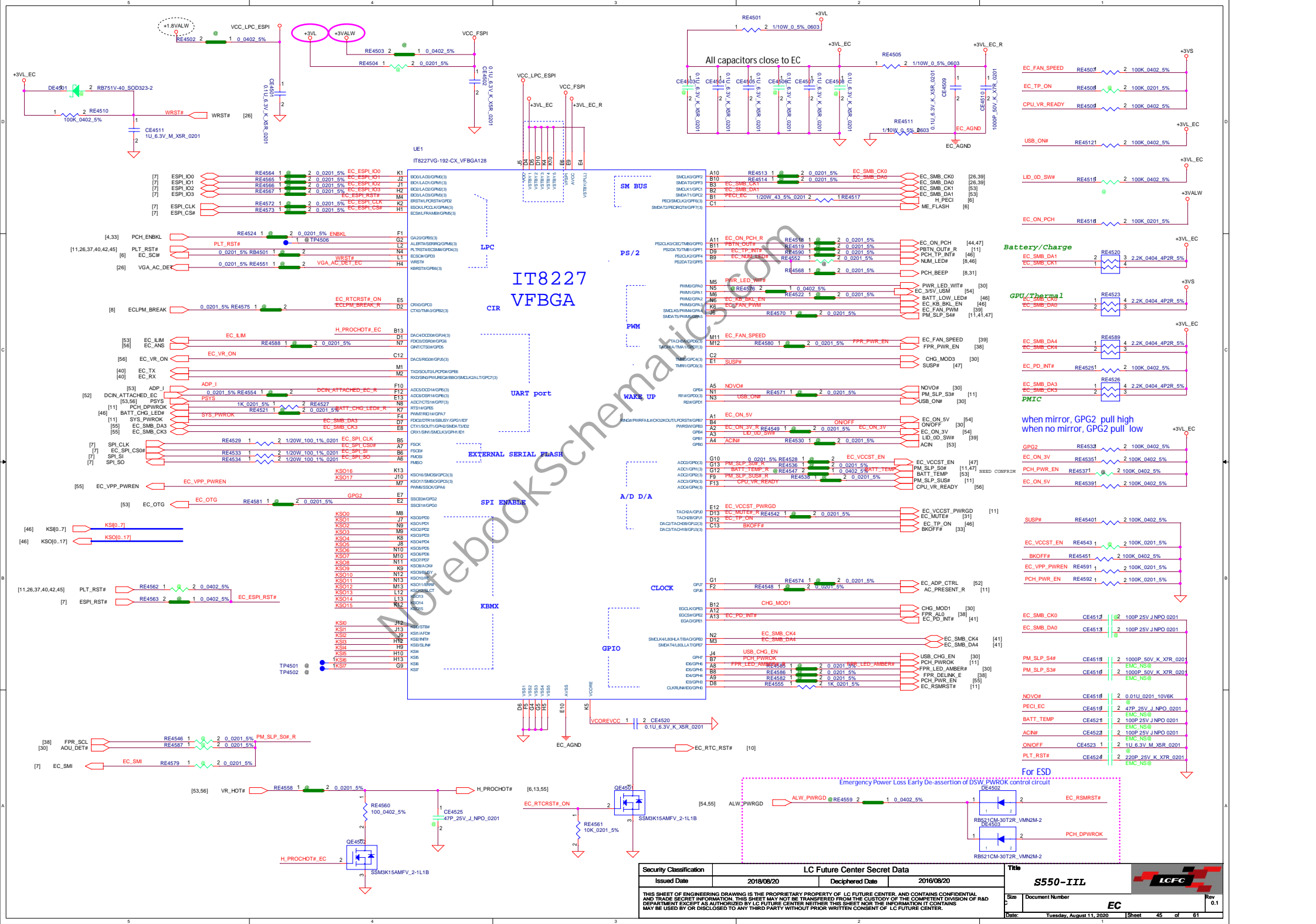


IN
IN
OUT

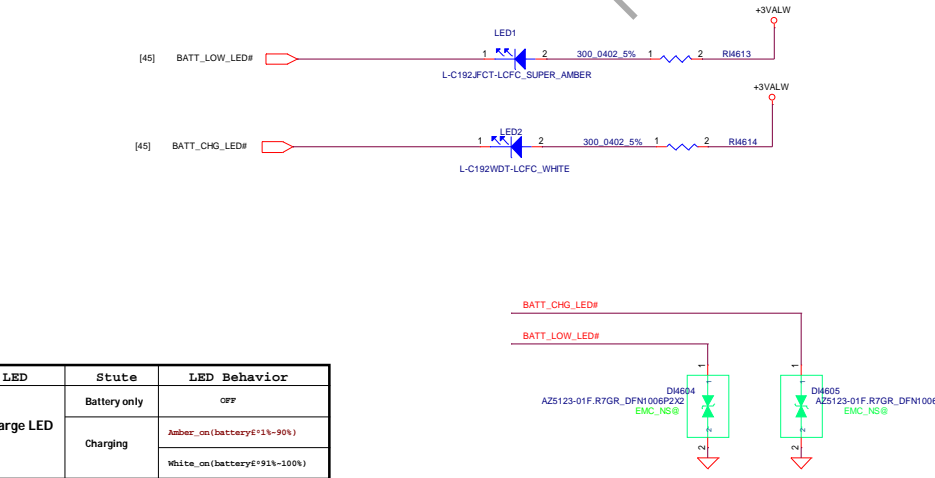
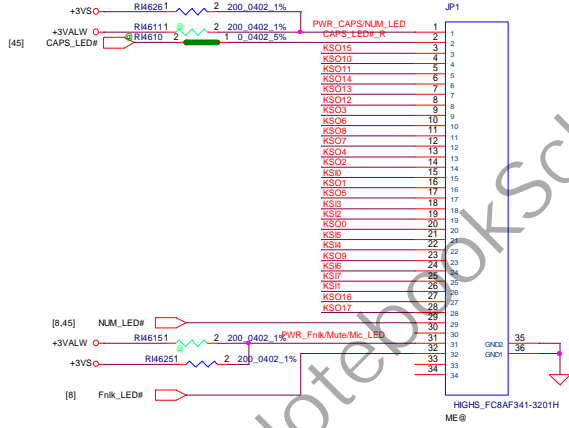
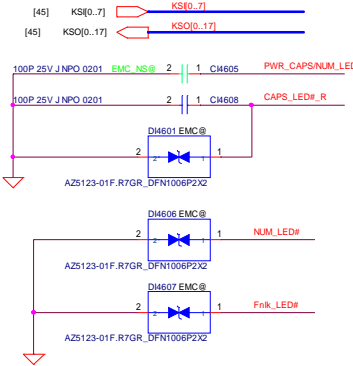


Share Same GND plane and connect to M2 & M3 pins (SVR_VSS) of BB

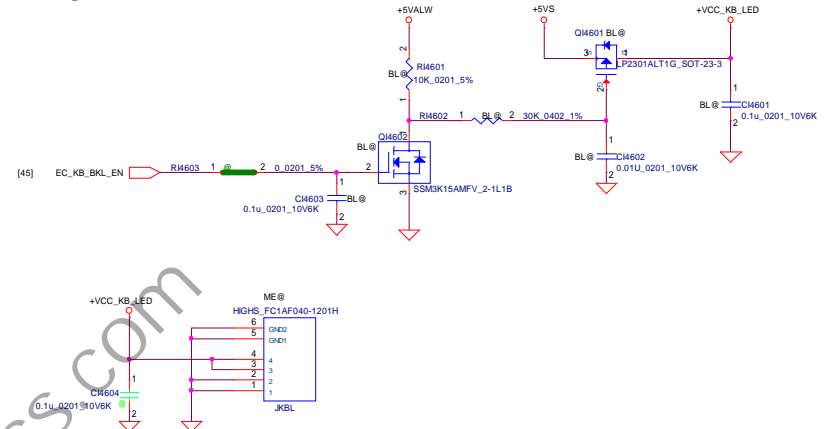




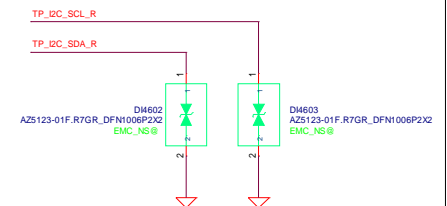
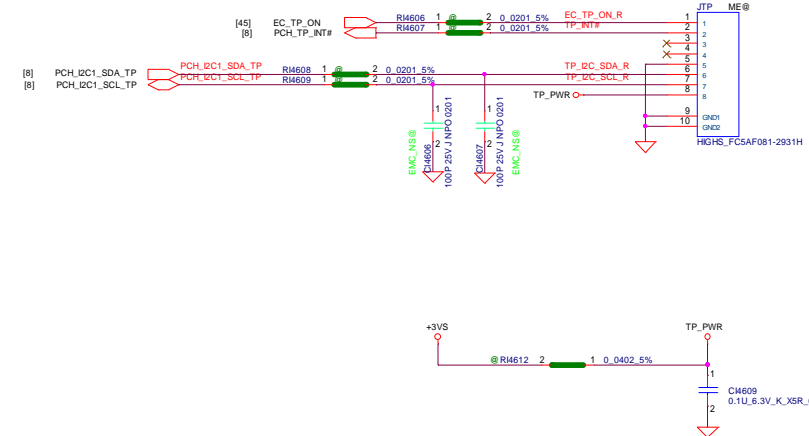
K/B Connector




KB Backlight Connector

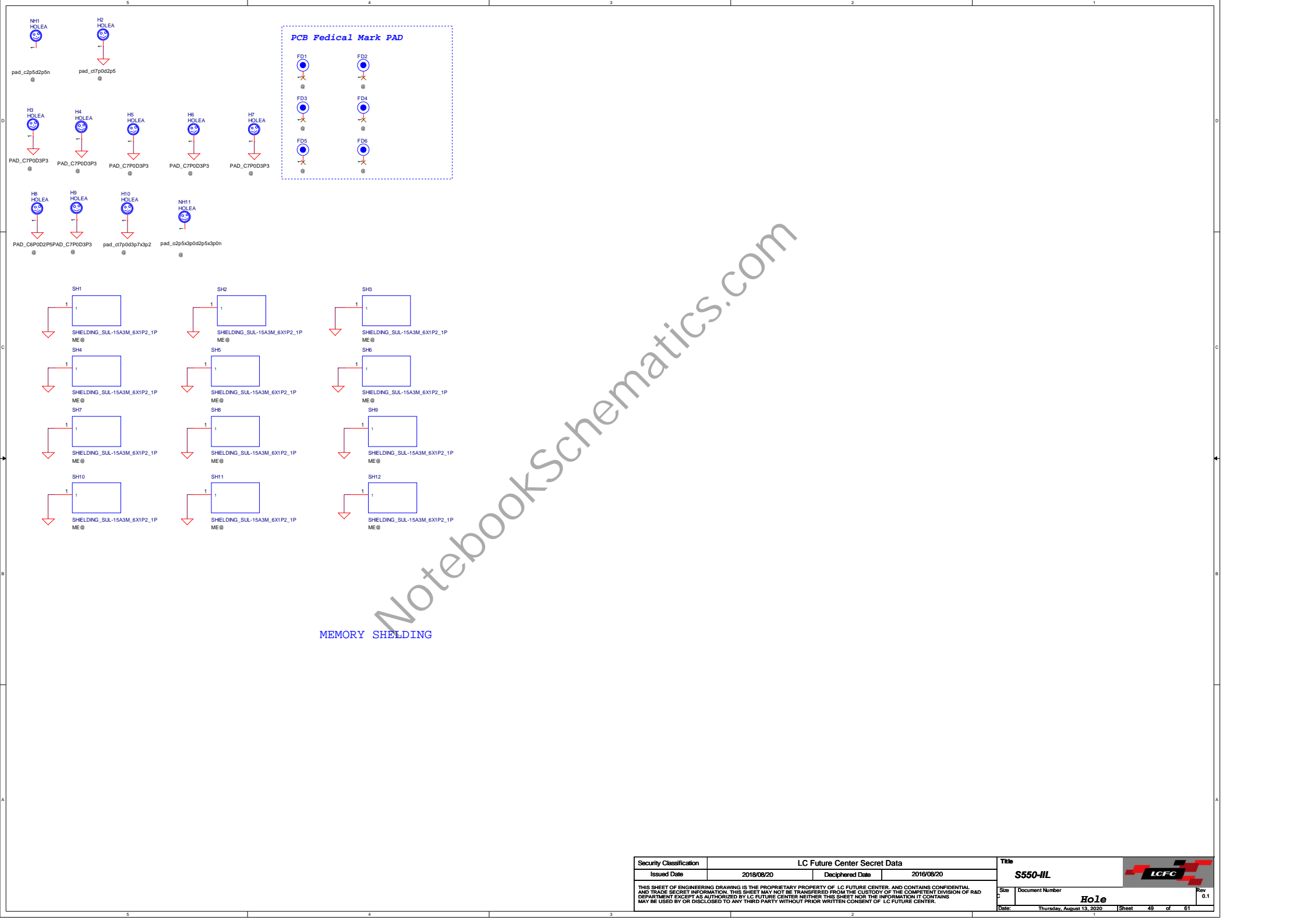


TP/B Connector

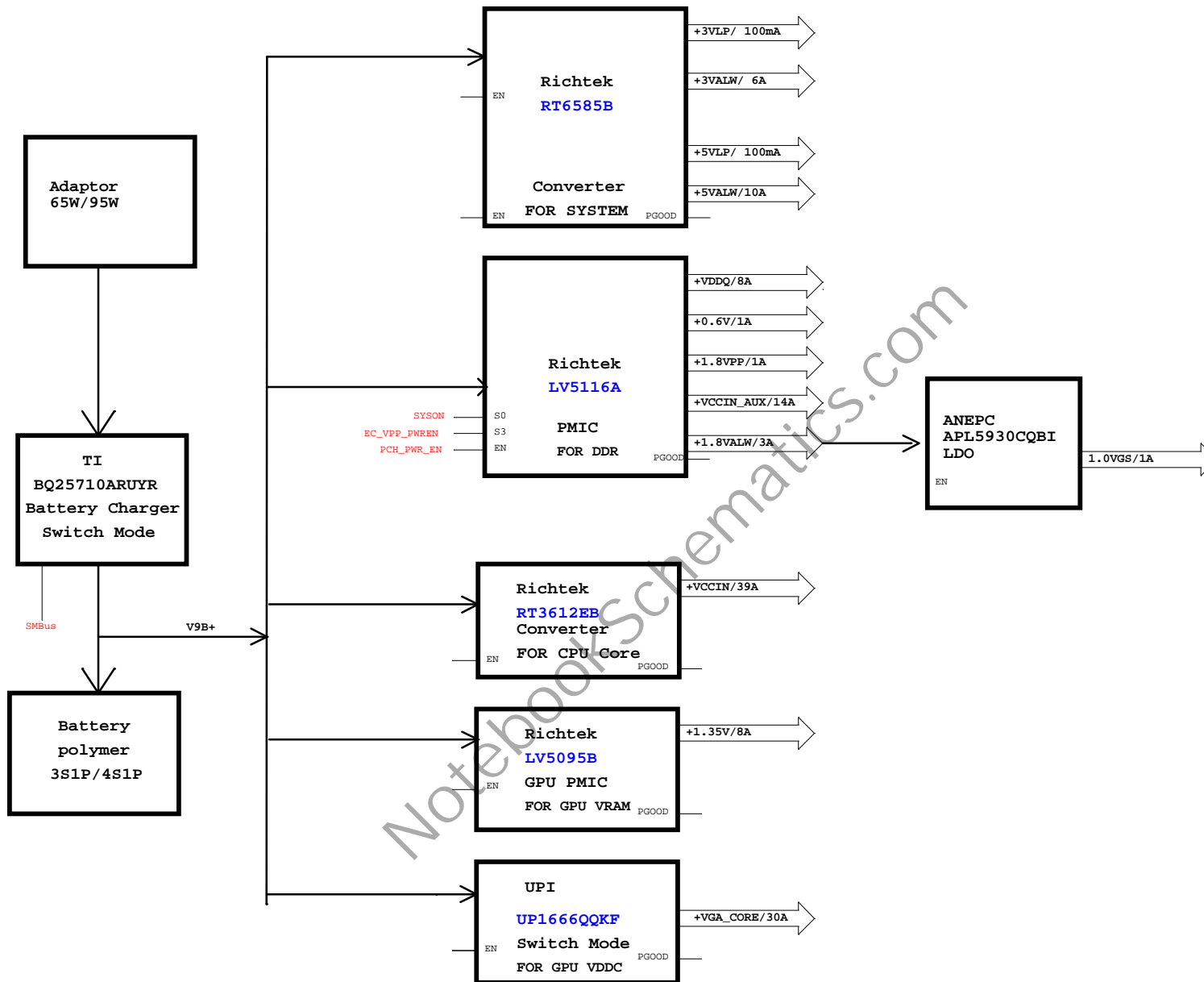


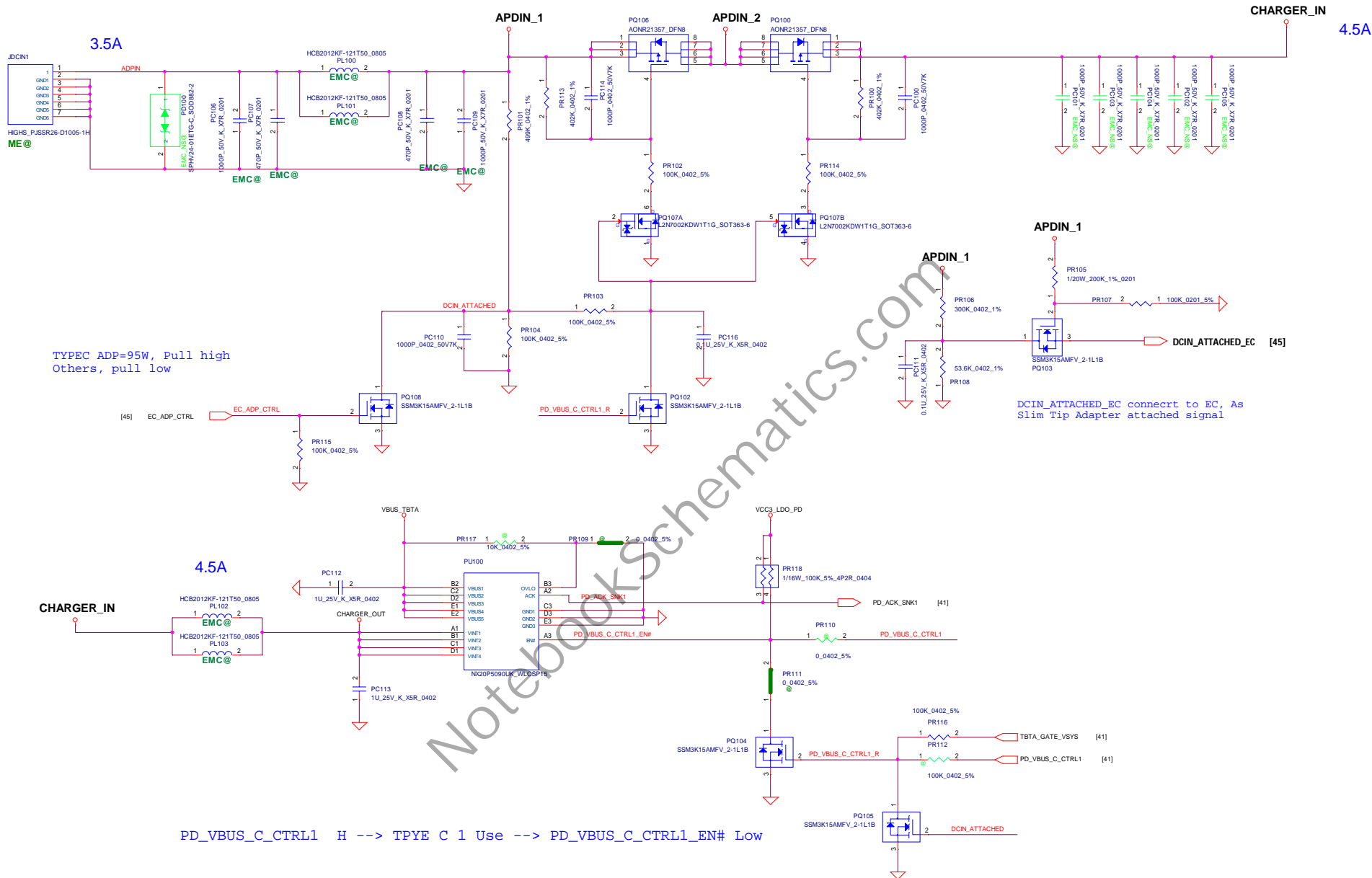
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C					0.1	
Date: Thursday, May 28, 2020						Sheet 48 of 61

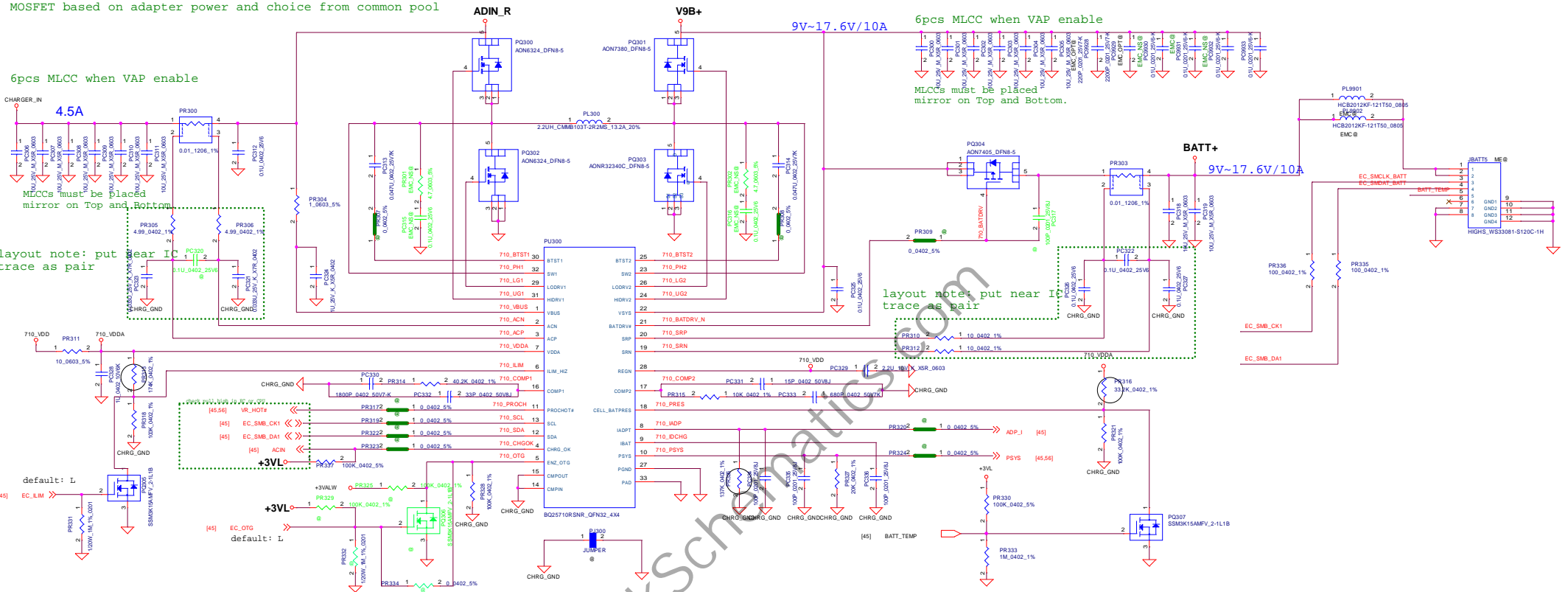


MEMORY SHIELDING





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layout note: put
trace as pair
```



IDPM	V(ILIM)	PR313
500mA	1.2V	402K
1.0A	1.4V	332K
1.5A	1.6V	280K
2.0A	1.8V	237K
3.0A	2.2V	174K
3.25A	2.3V	162K
4.0A	2.6V	162K


$$V_{ILIM} = 1V + 40x(V_{ACP} - V_{ACN}) = 1 + 40xIDPM \times R_{AC}$$

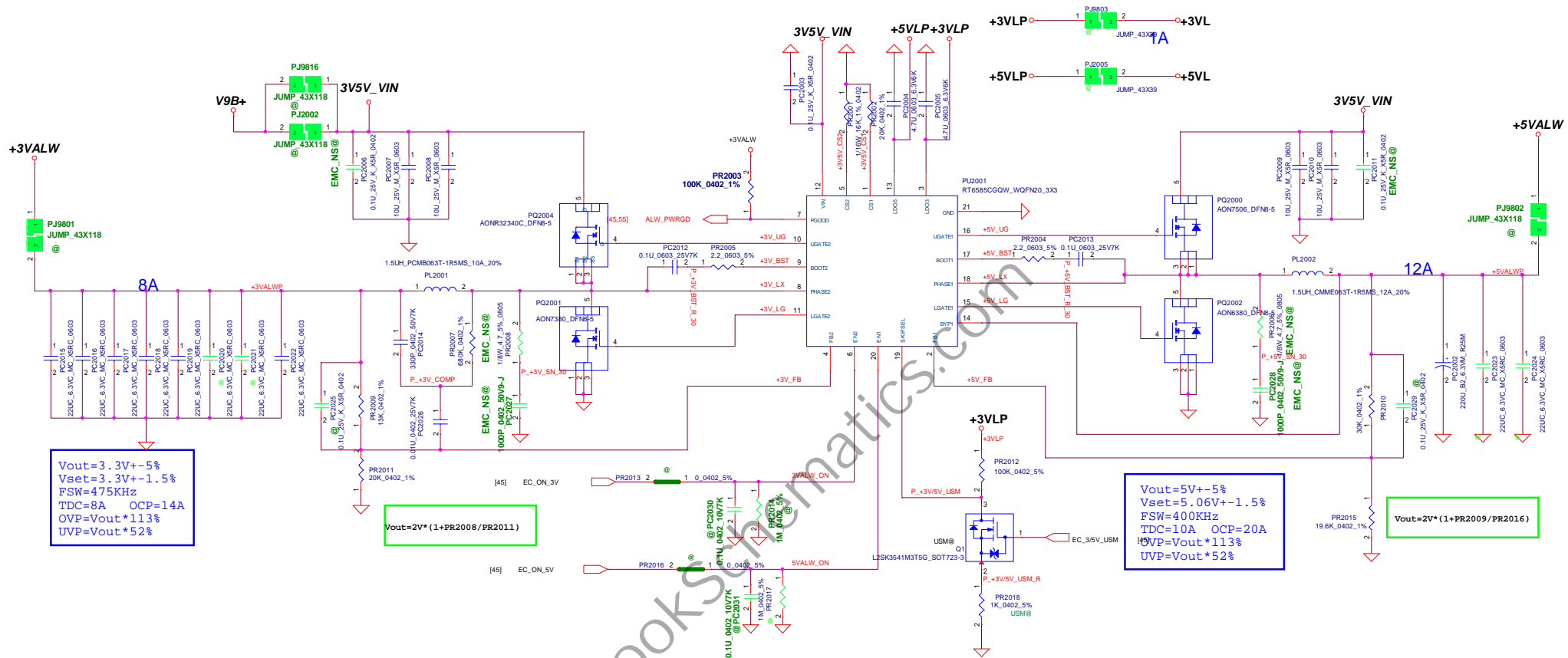
IND IN USE	PR326
1uH	93K
2.2uH	137K
3.3uH	169K

← LOGIC

# of CELL	VCELL_PRES	PR316
1-CELL	1.5V	301K
2-CELL	2.4V	150K
3-CELL	3.3V	82K
4-CELL	4.5V	33.2K

LOGIC

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				Date		Rev	
				Thursday, July 30, 2020		1.0	
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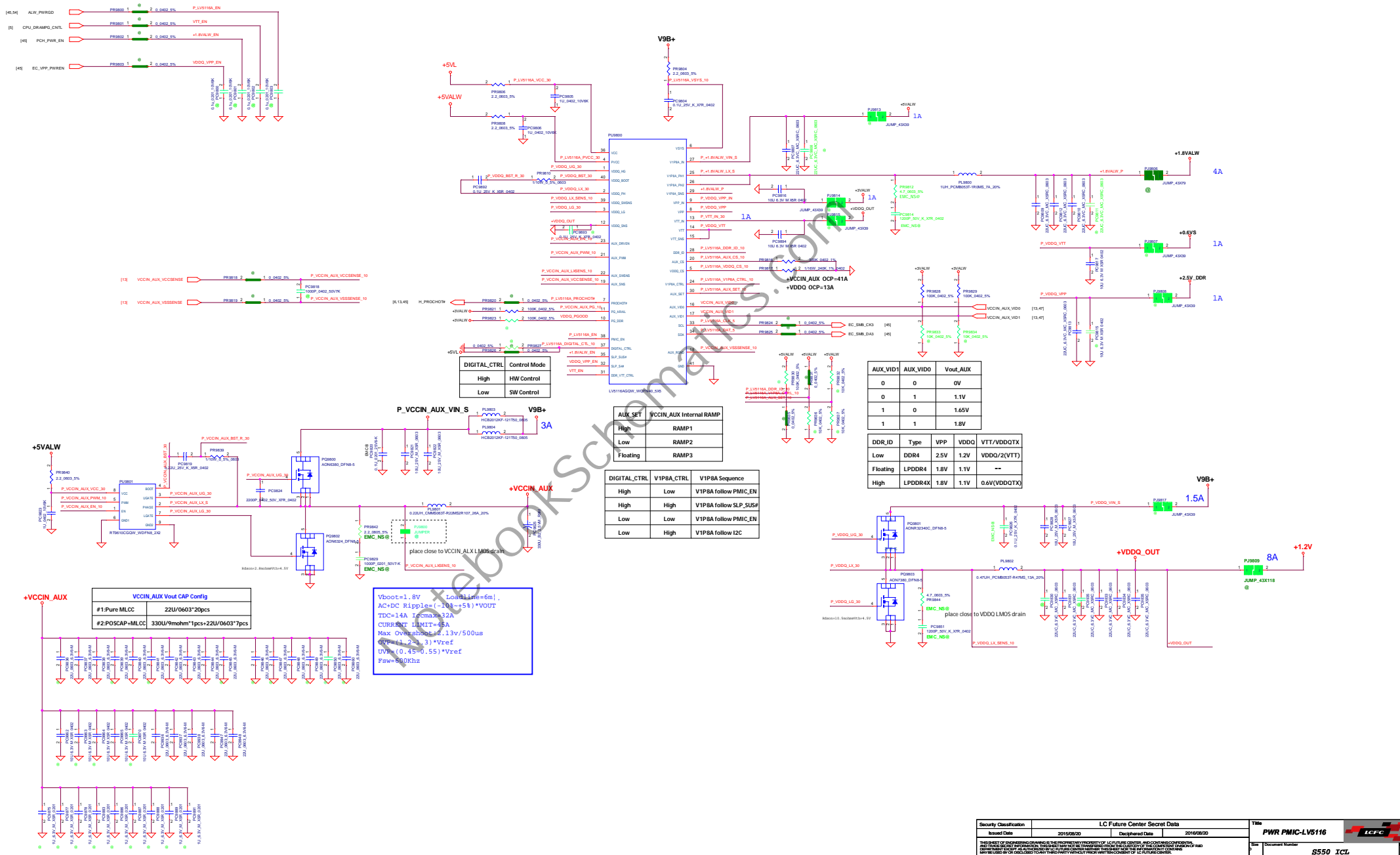


	RT6585B&TPS51285B	RT6575D&TPS51275B
Mode	DEM/CCM	USM/CCM
3V FSW	475K	355K
5V FSW	400K	300K
CSx	$R_{limit} = (I_{limit} * R_{dson}) * 8 / 50uA$	$R_{limit} = (I_{limit} * R_{dson}) * 8 / 10uA$

RT6585B&TPS51285B BOM to BOM

RT6575D&TPS51275B BOM to BOM

RT6585B&RT6575D PIN to PIN, with different work mode, FSW, and CS setting



DIGITAL_CTRL	Control Mode
High	HW Control
Low	SW Control

AUX_SET	VCCIN_AUX Internal RAMP
High	RAMP1
Low	RAMP2
Floating	RAMP3

DIGITAL_CTRL	V1PBA_CTRL	V1PBA Sequence
High	Low	V1PBA follow PMIC_EN
High	High	V1PBA follow SLP_SUS#
Low	Low	V1PBA follow PMIC_EN
Low	High	V1PBA follow I2C


AUX_VID1	AUX_VID0	Vout_AUX
0	0	0V
0	1	1.1V
1	0	1.65V
1	1	1.8V

DDR_ID	Type	VPP	VDDQ	VTT/VDDQTX
Low	DDR4	2.5V	1.2V	VDDQ/2(VTT)
Floating	LPDDR4	1.8V	1.1V	--
High	LPDDR4X	1.8V	1.1V	0.6V(VDDQTX)

VCCIN_AUX Vout CAP Config	
#1-Pure MLCC	22u/0.603"20pcs
#2-POSCAP-MLCC	330u/9mohm*1pcs+22u/0.603"7pcs

Vboot=1.8V
AC-DC Ripple=($I_{OUT} \times 58$)*VOUT
TDC=14A
I_{CP}=32A
CURRENT LIMIT=45A
Max Overshoot=14.13V/500us
C_{IN}=(1.2-1.3)*Vref
UV_{IN}=(0.45-0.55)*Vref
Psw=600Khz

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20200513
1. P045: GPF4 change form CAPS_LED# to PCH_TP_INT# add RE4590
2. P06: GPP_A13 change form FB_GCo_EN_R to PCH_BT_OFF#
3. P08: Remove GPP_C13 PCH_BT_OFF#
4. P40: Add ON3&RN30&RN29 for level shift to PCH_BT_OFF#

20200514
1. P033: Add 100pf cap CG3421 on DMIC_CLK
2. P08: Add PU on CAPS_LED#/Fnlk_LED#/NUM_LED#
3. P055 Add 3*22u cap on VCCIN_AUX PC9936/PC9937/PC9938
4. P056 ADD 8*22u cap

20200518
1. P11: Add PD Resistor on Sleep_wlan RC1138
2. P45: Add PD Resistor on VPP_EN/PCH_POWER_EN RE4591/RE4592
3. P40: RN4009 change net name

20200520
1. P07: SPI ROM Co-lay

20200525
1. P55: Add 2*22U cap on VCCIN_AUX
2. Add NCTF test pad PIN DW51, DV52, DP53, DV1, DN1, B52, A49, B2

20200526
1. P07: change SPI ROM Colay
2. remove NCTF test pad TP4507&TP4511

20200624
1. P41 Remove L4401, L4402, L4403, L4404
2. P41 change RB4433, RB4405, RB4410, RB4416, RB4417, RB4413, RB4414, RB4415 from 0ohm to 2.2ohm

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